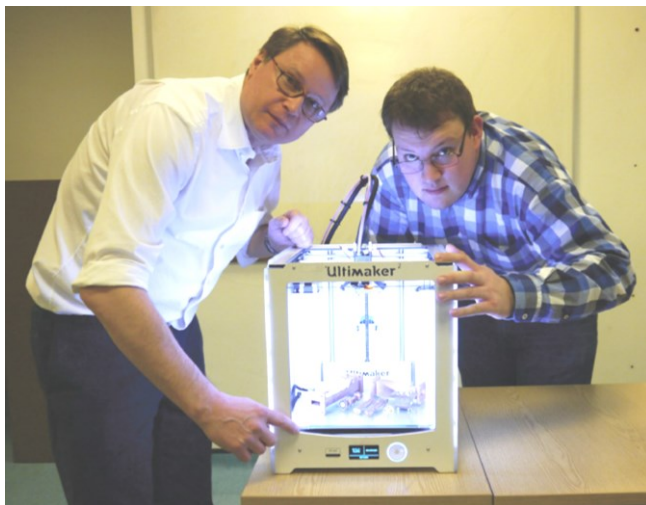


Building-Edge Additive Manufacturing Technologies: 3D Printing Landscape for Next Generation Radio Frequency Applications



Stepan Lucyszyn

August 2023



Motivations

- Additive manufacturing minimizes material waste
- Polymer-based 3D-printing delivers dramatic mass reduction (saving transportation energy)
- Polylactic acid (PLA) is made from starch and so biodegradable
- Easily accessible technology to the general public (becoming more ubiquitous)
- Replacement part manufacture within isolated/remote communities
- Rapid prototyping and small-batch production saves time and money
- Promotes in-house innovation (securing intellectual property rights)
- Excellent pedagogical tool for hands-on students
- Enables tactile and visual observation of complex 3D geometries



Environmental



Social



Governance



Educational

Impact

- Drones for agricultural monitoring (millimetre-wave radiometric imaging payloads)
- Earth observation satellites for pollution monitoring (millimetre-wave spectrometry payloads)
- +5G connectivity in remote locations using low-altitude balloons (communications payloads)
- Global +6G coverage with mega satellite constellations (communications payloads)
- Ubiquitous medical diagnostic equipment in GP surgeries and clinics (radiometric imaging of skin)
- Support emergency services using aerial vehicles (imaging and communications payloads)
- Ubiquitous security screening for weapons/contraband (radiometric imaging stand-off detection)
- Low-cost research infrastructure (avoiding expensive cleanroom facilities)
- Innovative technology transfer between academia and industry
- World-class research and highly skilled workforce for new spin-out SMEs



Environmental



Social

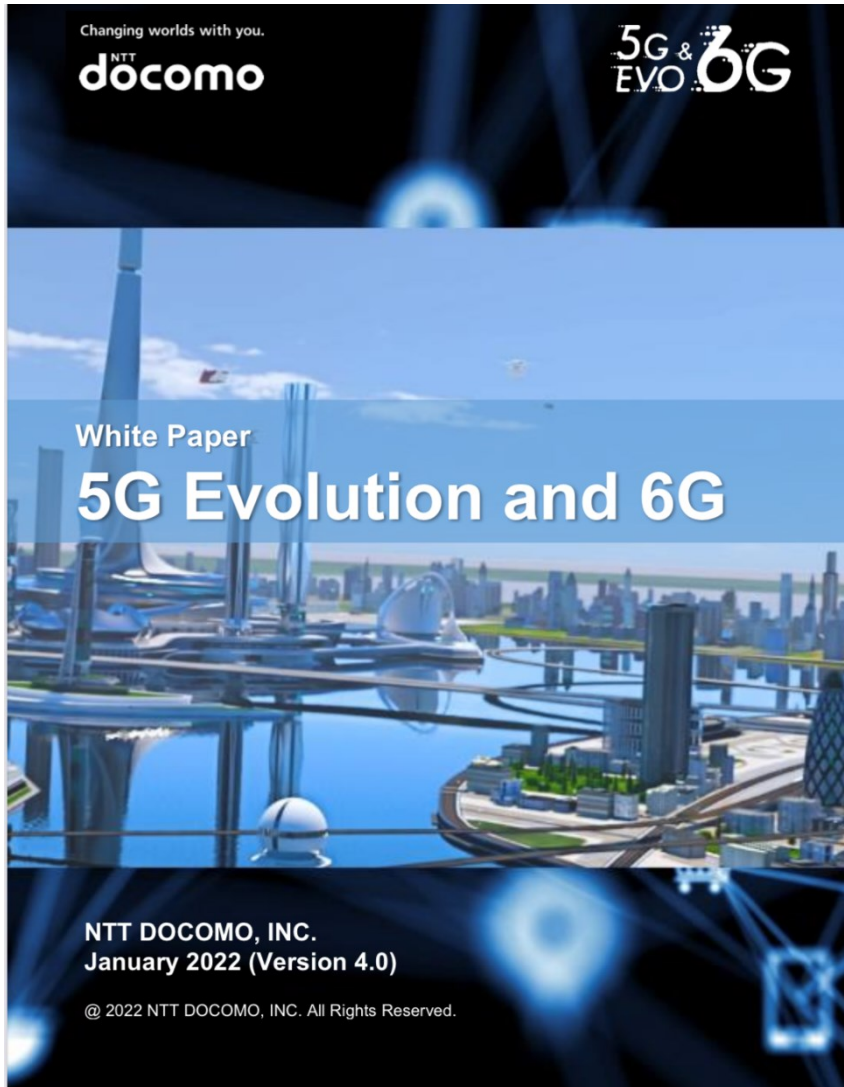


Governance

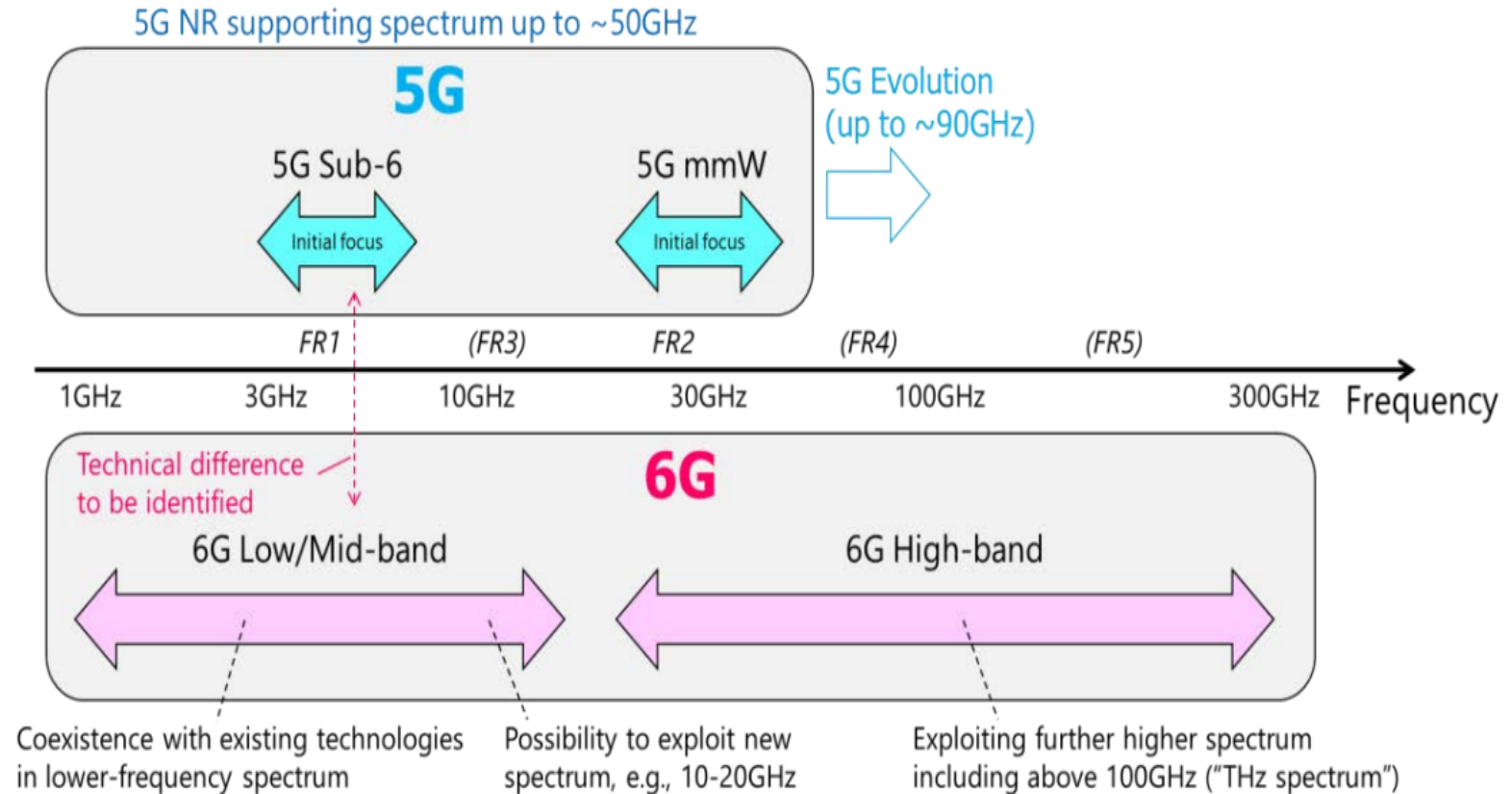


Educational

Motivations for G-band (140 to 220 GHz)



NTT to Pilot 6G Network at 2025 Osaka World Expo!



Low-cost 3D-printing Facilities

Formlabs Form 3 Laser SLA Raise3D Pro 2 FDM

Fume Hood With
Elegoo Mars MSLA



Above: Ventilated Partial Enclosure
Below: Vodex Fume Extractor

Our MSLA 3D Printers

£280 May 2021

**Elegoo Mars 2 Pro:
50 μm resolution**



Old Workhorse

£318 September 2021

**Phrozen Sonic Mini 4k:
35 μm resolution**



Current Workhorse

£592 January 2022

**Phrozen Sonic Mini 8k:
22 μm resolution**



New Arrival

IEEE TRANSACTIONS ON COMPONENTS, PACKAGING AND MANUFACTURING TECHNOLOGY, VOL. 5, NO. 9, SEPTEMBER 2015

1339

3-D Printed Metal-Pipe Rectangular Waveguides

Mario D'Auria, *Student Member, IEEE*, William J. Otter, *Member, IEEE*, Jonathan Hazell,
Brendan T. W. Gillatt, Callum Long-Collins, Nick M. Ridler, *Fellow, IEEE*,
and Stepan Lucyszyn, *Fellow, IEEE*

2 Undergraduate
Project Students

<https://eps.ieee.org/publications/enews/JDecember-1021/579-most-popular-t-cpmt-articles.html>

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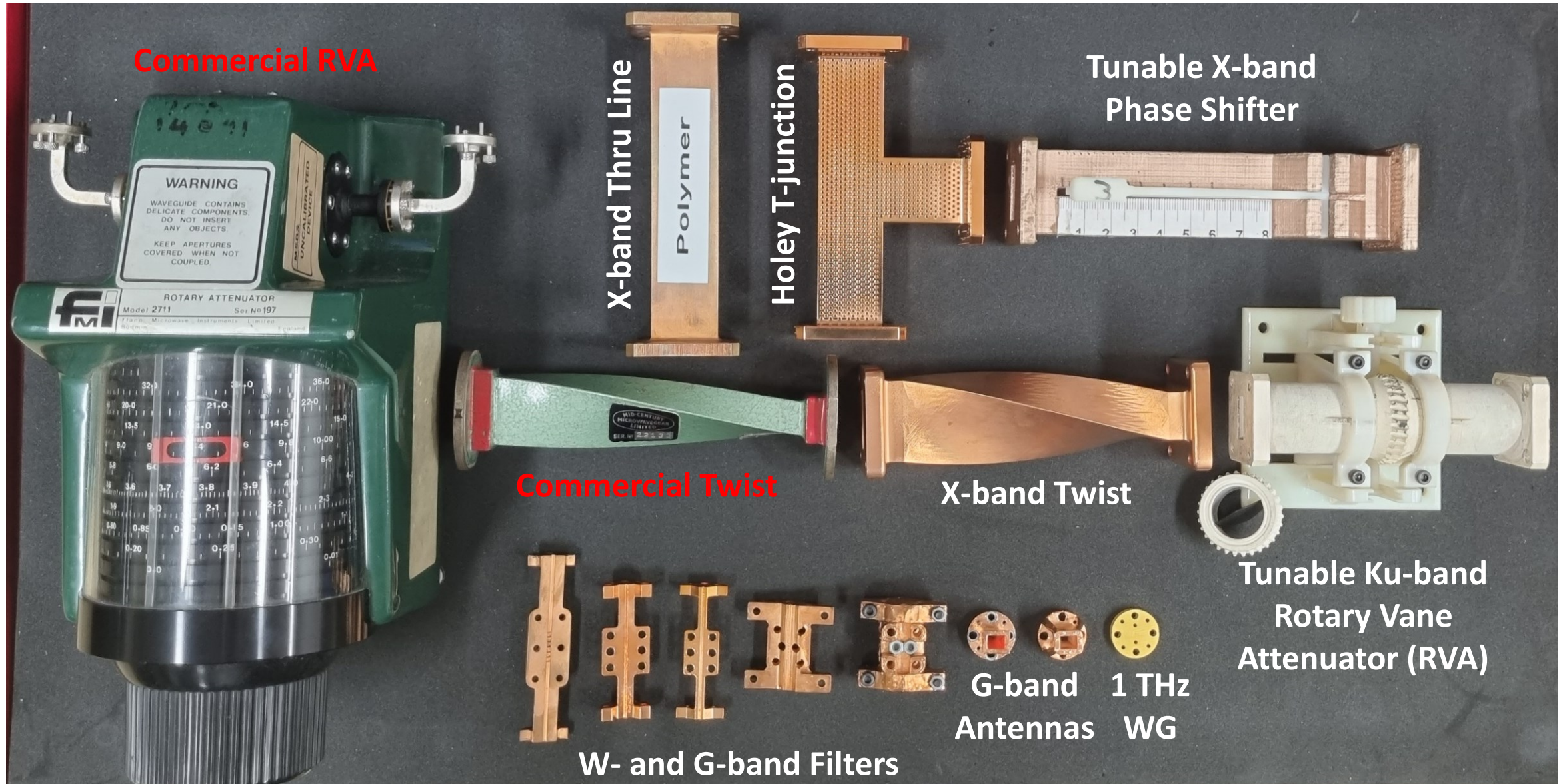
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Most Popular T-CPMT Articles

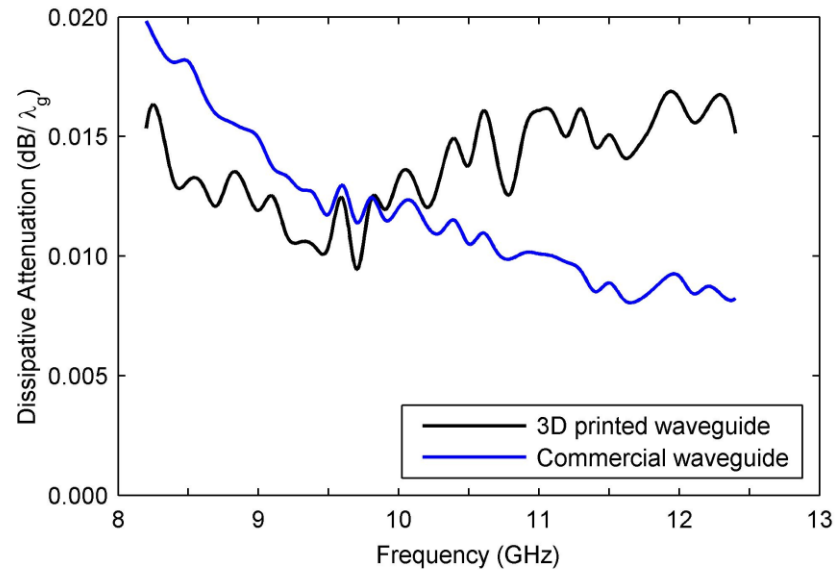
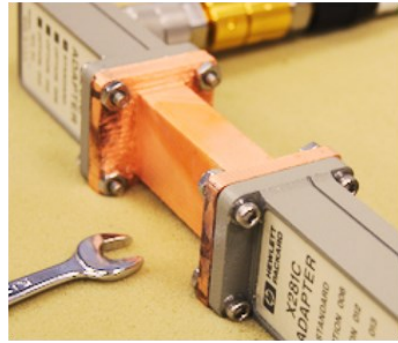
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3-D Printed Metal-Pipe Rectangular Waveguides

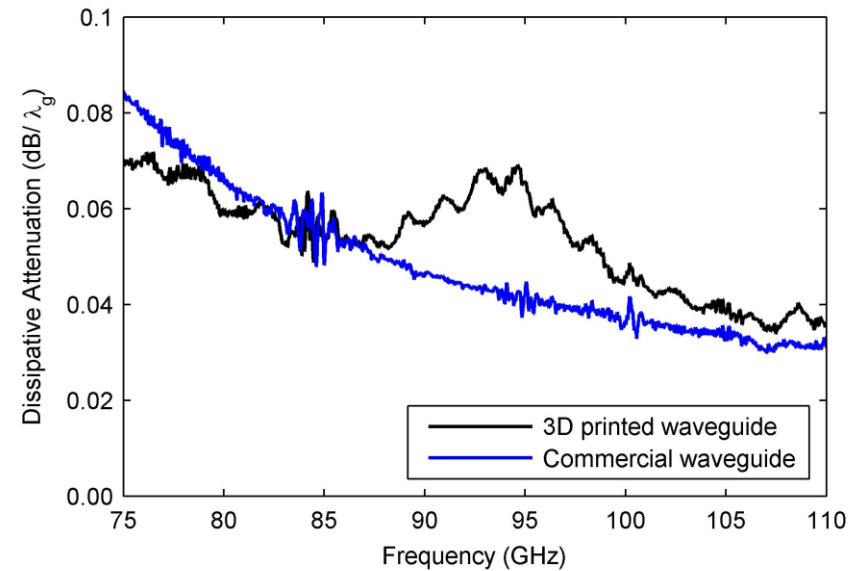
Mario D'Auria ; William J. Otter ; Jonathan Hazell ; Brendan T. W. Gillatt ; Callum Long-Collins ; Nick M. Ridler ; Stepan Lucyszyn
Publication Year: 2015, Page(s): 1339 – 1349



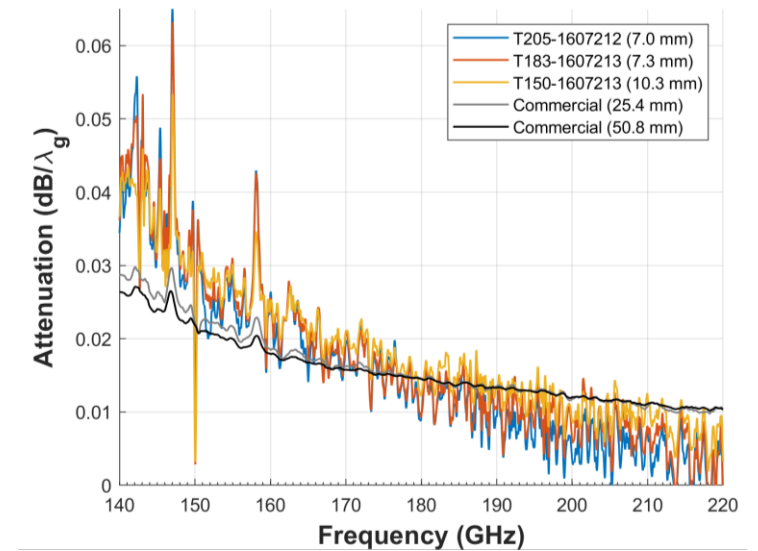
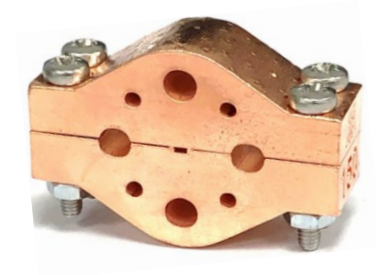
X-band (8 to 12 GHz)



W-band (75 to 110 GHz)




G-band (140 to 220 GHz)




Measurement 158 (2020) 107682


Contents lists available at [ScienceDirect](#)

 **ELSEVIER**

Measurement

journal homepage: www.elsevier.com/locate/measurement

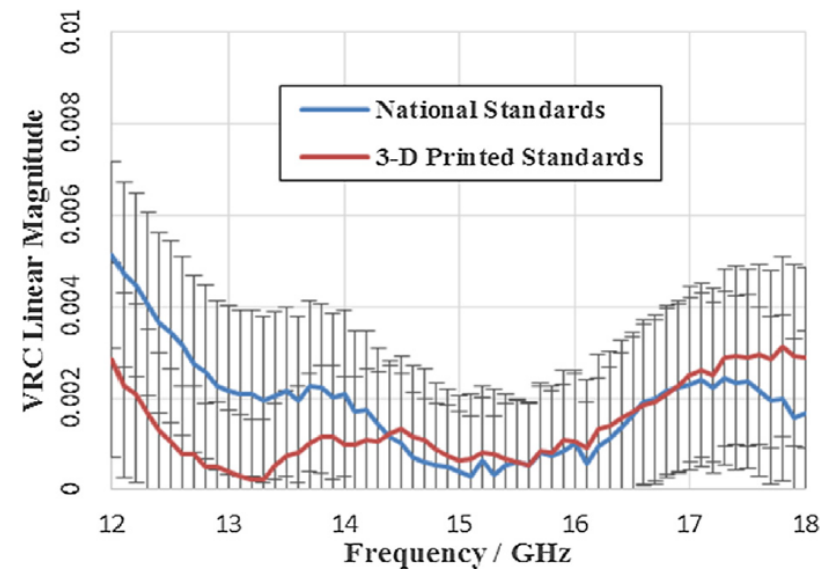
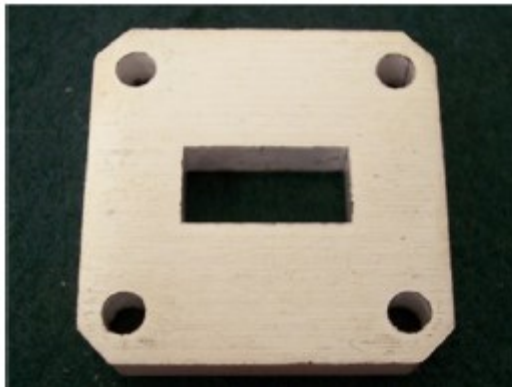


3-D printed primary standards for calibration of microwave network analysers 

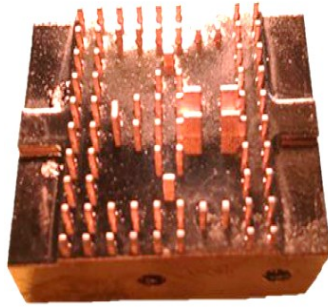
Adam Jones^a, Stepan Lucyszyn^b, Enrique Márquez-Segura^c, Nick Ridler^{a,*}, James Skinner^a, Daniel Stokes^a

^a National Physical Laboratory (NPL), Hampton Road, Teddington TW11 0LW, UK
^b Imperial College London, Exhibition Road, London SW7 2AZ, UK
^c Universidad de Málaga, Av. de Cervantes, 2, 29016 Málaga, Spain

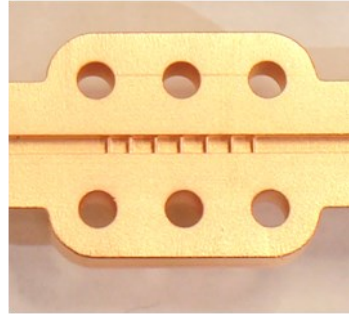
Pre-university
Apprentice



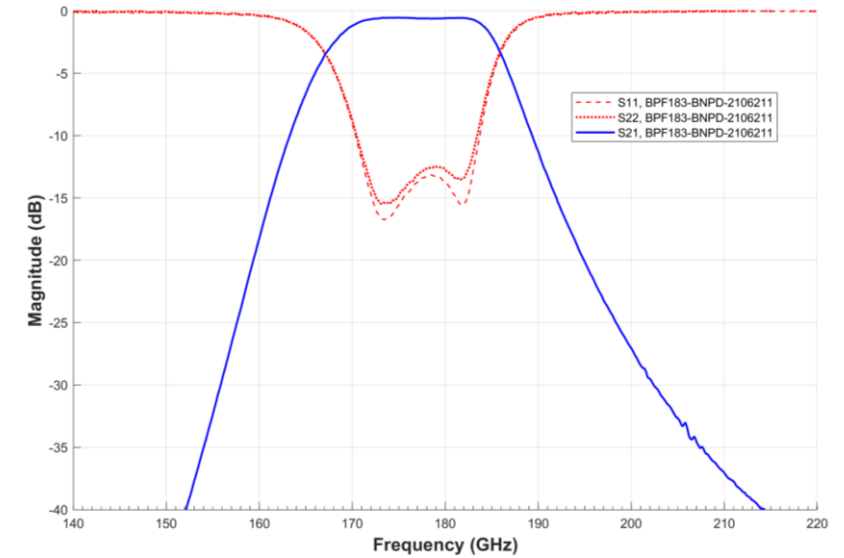
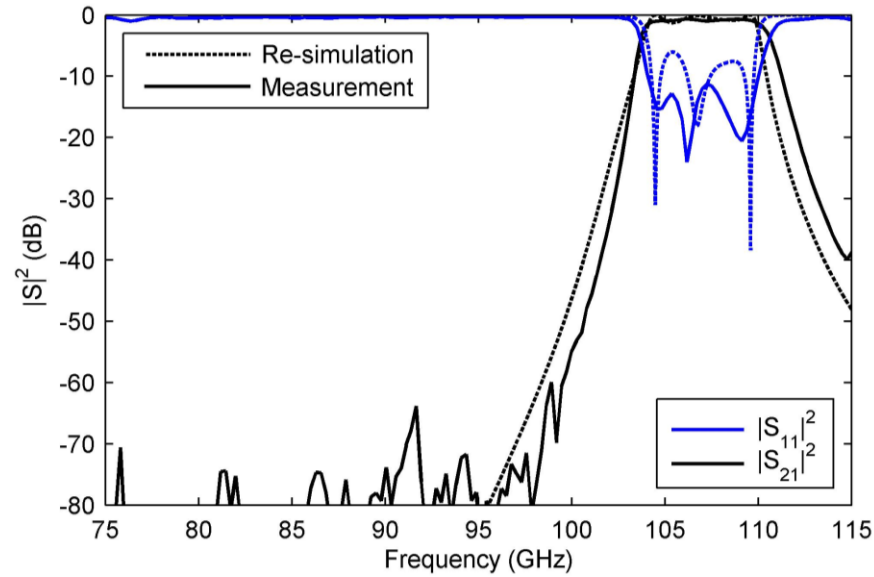
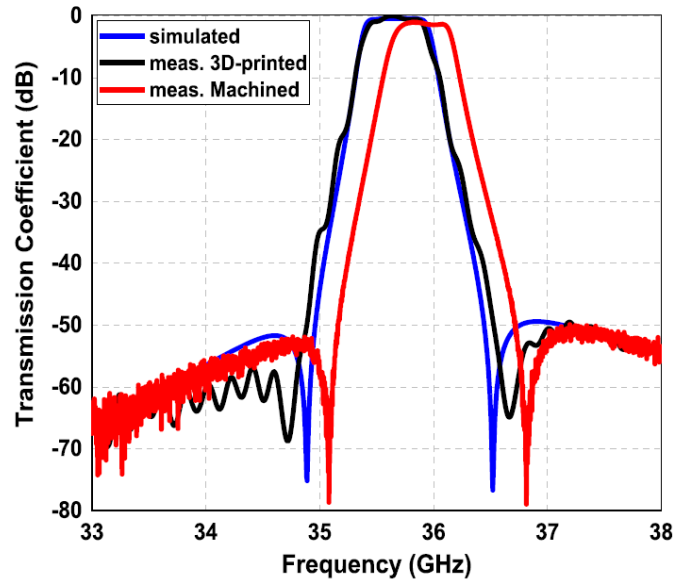
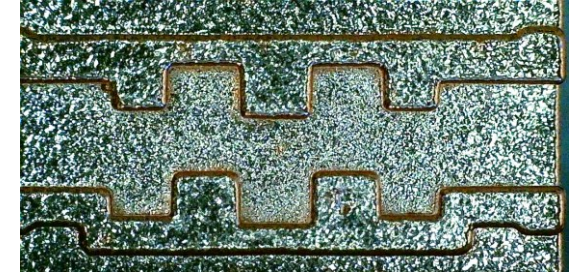
Ka-band



W-band



G-band



G-band (140 to 220 GHz) Manufacturing Limits

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Received January 24, 2022, accepted March 23, 2022, date of publication March 28, 2022, date of current version April 15, 2022.

Digital Object Identifier 10.1109/ACCESS.2022.3162586

3-D Printing Quantization Predistortion Applied to Sub-THz Chained-Function Filters

**LIYAN ZHU¹, ROSHAN PAYAPULLI¹, SANG-HEE SHIN¹, (Member, IEEE),
MANOJ STANLEY², (Member, IEEE), NICK M. RIDLER², (Fellow, IEEE),
AND STEPAN LUCYSZYN¹, (Fellow, IEEE)**

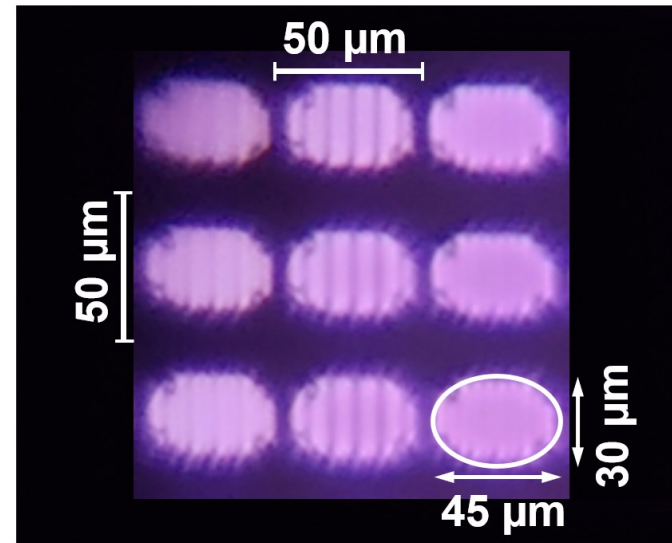
¹Department of Electrical and Electronic Engineering, Imperial College London, London SW7 2AZ, U.K.

²Department of Electromagnetic and Electrochemical Technologies, National Physical Laboratory, Teddington TW11 0LW, U.K.

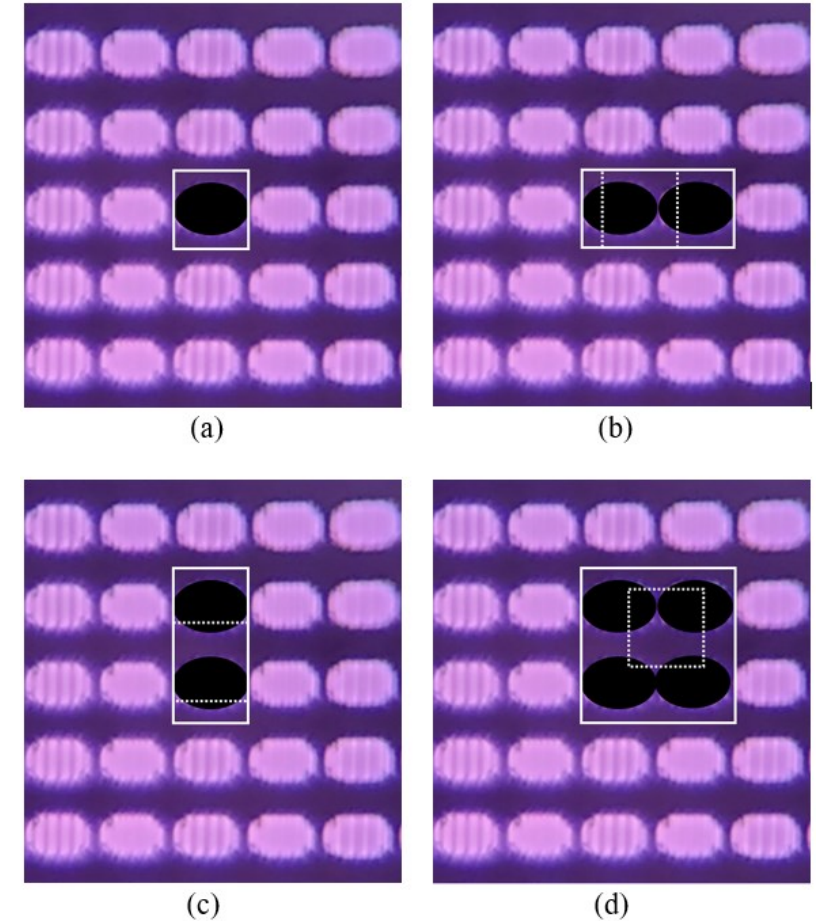
Corresponding author: Stepan Lucyszyn (s.lucyszyn@imperial.ac.uk)

This work was supported by the U.K. Space Agency's Centre for Earth Observation Instrumentation (CEOI) under Grant RP10G0435A202.

Our masked stereolithography apparatus (MSLA)
Elegoo Mars 2 Pro, with 50 μm resolution and
print volume of 80 mm \times 129 mm \times 160 mm



$\lambda/2$ cavity resonator at 183.3 GHz has 8.5°
change in electrical length from 50 μm
quantization error \rightarrow 3.5% frequency shift



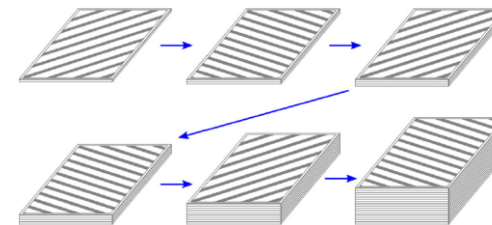
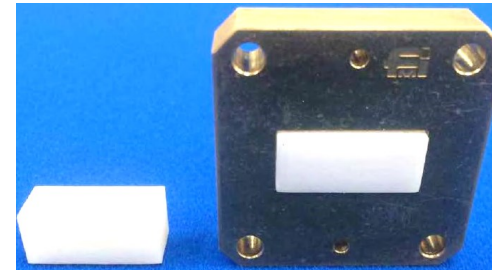
Registration errors between the
CAD drawing and slicing software

Received June 17, 2019, accepted June 29, 2019, date of publication July 4, 2019, date of current version August 1, 2019.

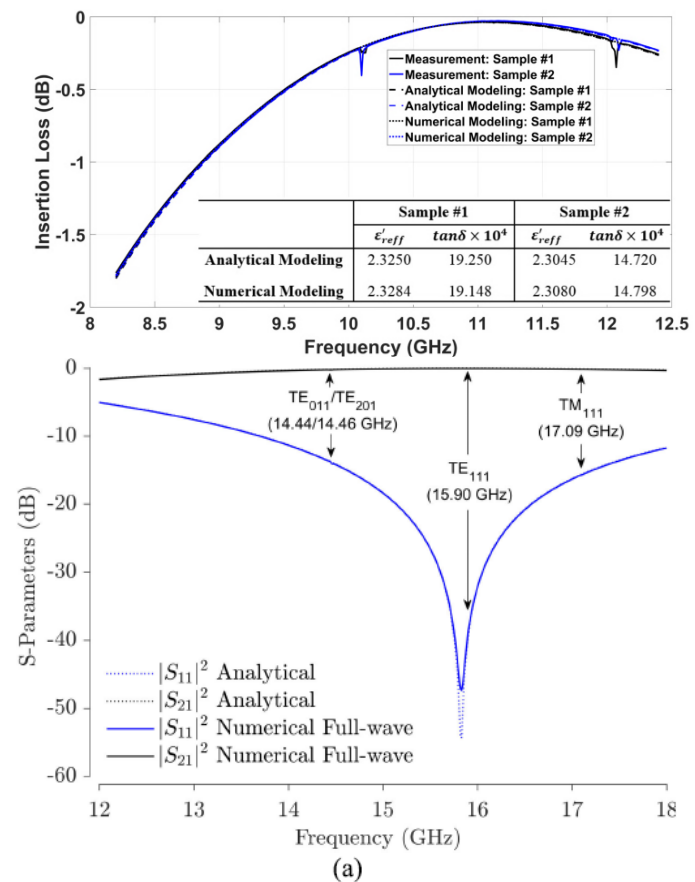
Digital Object Identifier 10.1109/ACCESS.2019.2926717

Microwave Characterization of Low-Loss FDM 3-D Printed ABS With Dielectric-Filled Metal-Pipe Rectangular Waveguide Spectroscopy

JINGYE SUN¹, ATTIQUE DAWOOD¹, WILLIAM J. OTTER¹,
NICK M. RIDLER², (Fellow, IEEE), AND STEPAN LUCYSZYN¹, (Fellow, IEEE)



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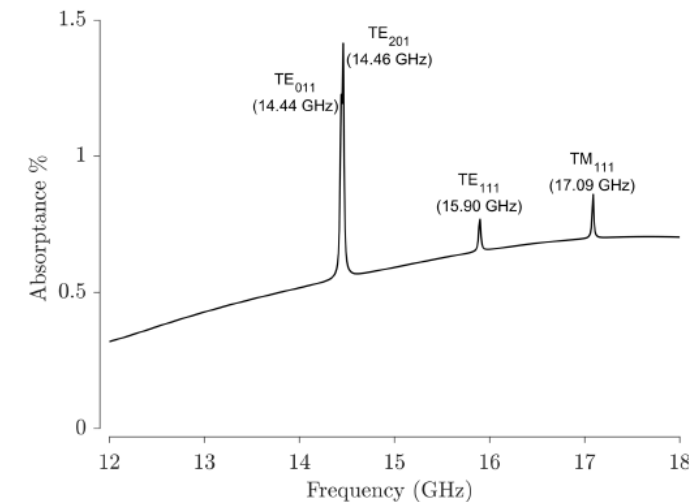


Received August 30, 2021, accepted September 8, 2021, date of publication September 10, 2021, date of current version October 6, 2021.

Digital Object Identifier 10.1109/ACCESS.2021.3111959

Parasitic High Q-Factor Open-Box Modes With 3-D Printed Dielectric-Filled Metal Waveguides

ATTIQUE DAWOOD AND STEPAN LUCYSZYN¹, (Fellow, IEEE)



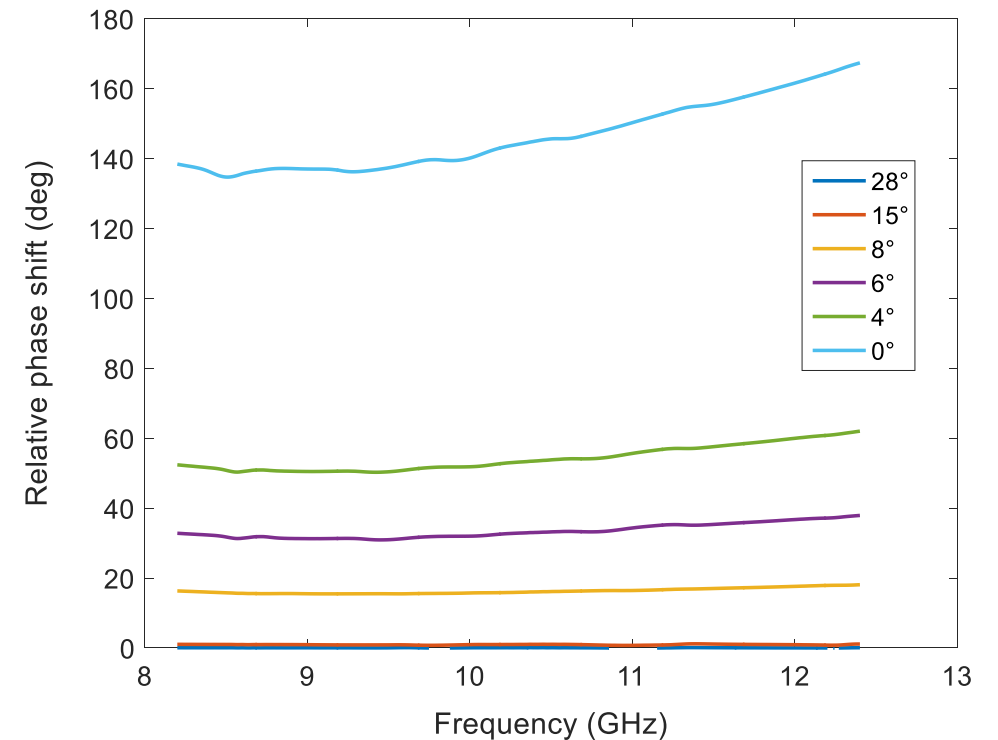
822

IEEE MICROWAVE AND WIRELESS COMPONENTS LETTERS, VOL. 26, NO. 10, OCTOBER 2016

3-D Printed Variable Phase Shifter

Brendan T. W. Gillatt, Mario D'Auria, William J. Otter, *Member, IEEE*,
Nick M. Ridler, *Fellow, IEEE*, and Stepan Lucyszyn, *Fellow, IEEE*

Undergraduate
Project Student



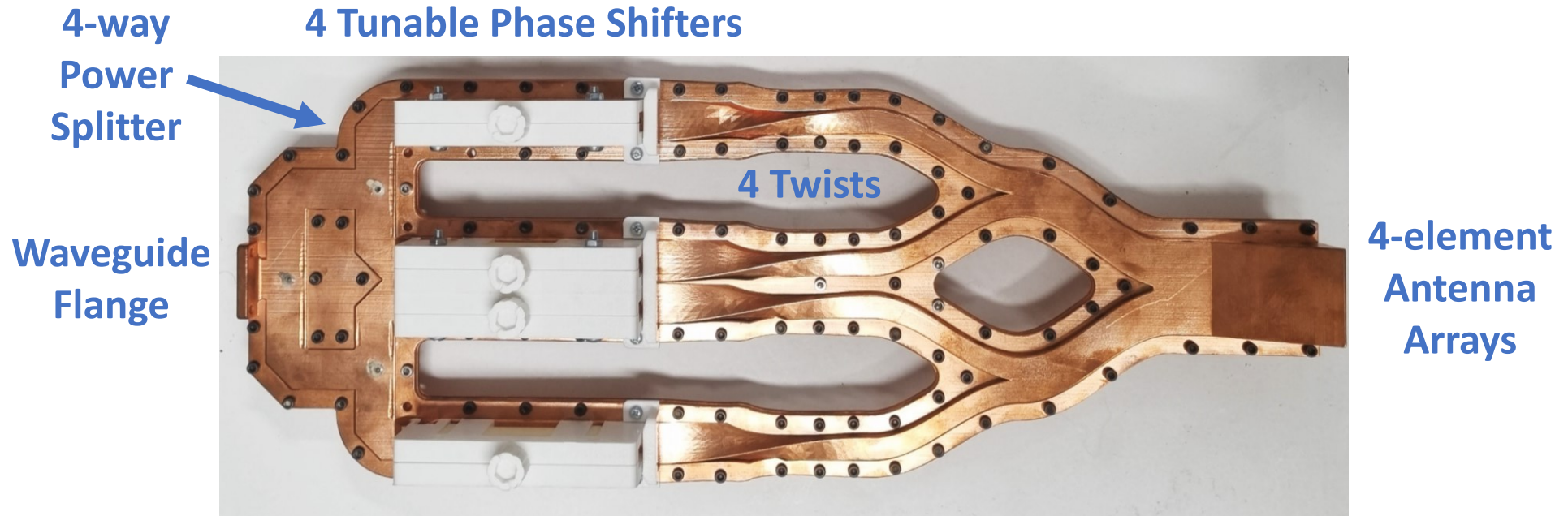
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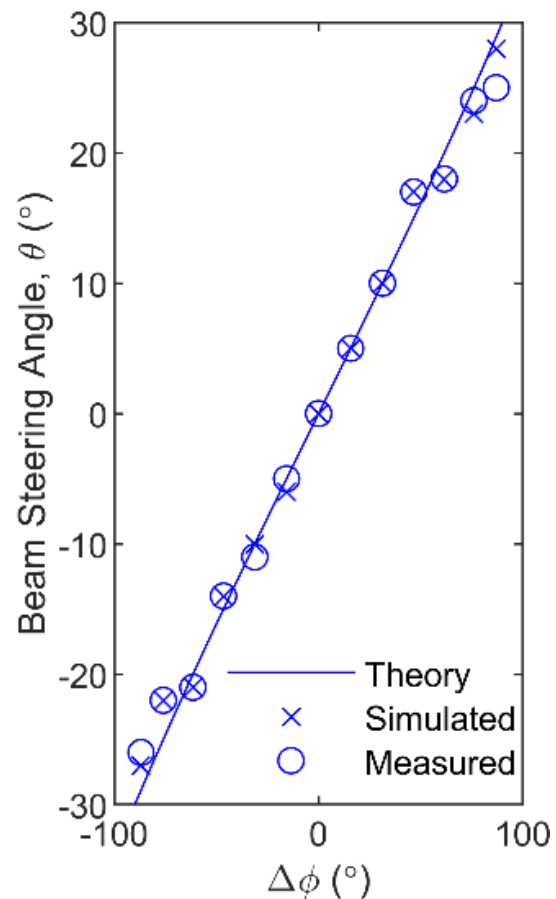
Received June 21, 2019, accepted July 24, 2019, date of publication August 1, 2019, date of current version August 16, 2019.
Digital Object Identifier 10.1109/ACCESS.2019.2932431

Polymer-Based 3-D Printed Ku-Band Steerable Phased-Array Antenna Subsystem

SANG-HEE SHIN¹, (Student Member, IEEE), DIYAR F. ALYASIRI¹, MARIO D'AURIA¹, WILLIAM J. OTTER¹, CONNOR W. MYANT², DANIEL STOKES³, ZHENGRONG TIAN³, NICK M. RIDLER³, (Fellow, IEEE), AND STEPAN LUCYSZYN¹, (Fellow, IEEE)

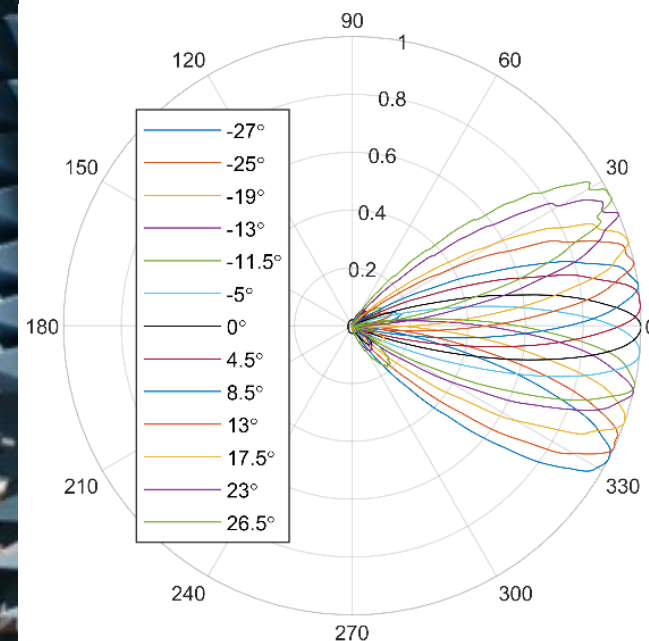
Undergraduate
Project Student

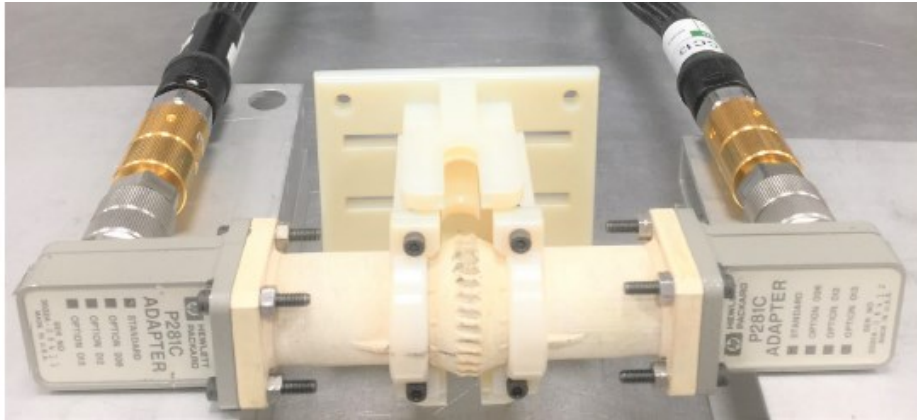




Standard Gain Horn

Phased Array Antenna



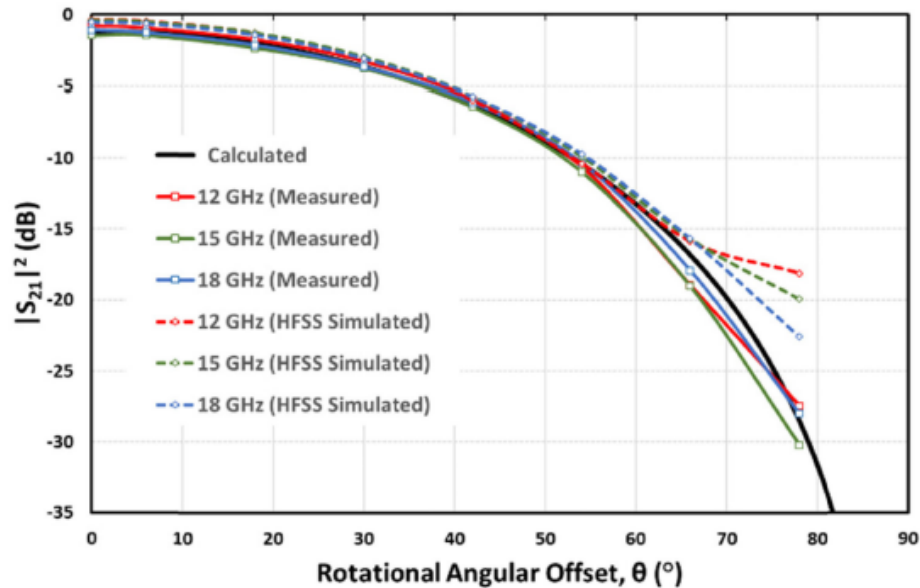


Received May 17, 2021, accepted May 31, 2021, date of publication June 7, 2021, date of current version June 17, 2021.

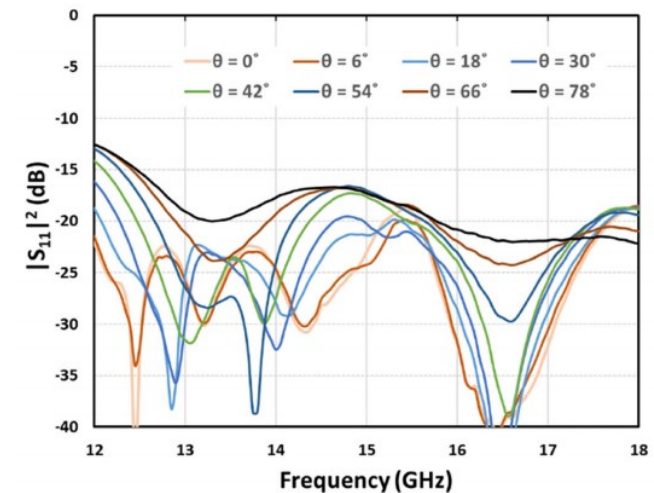
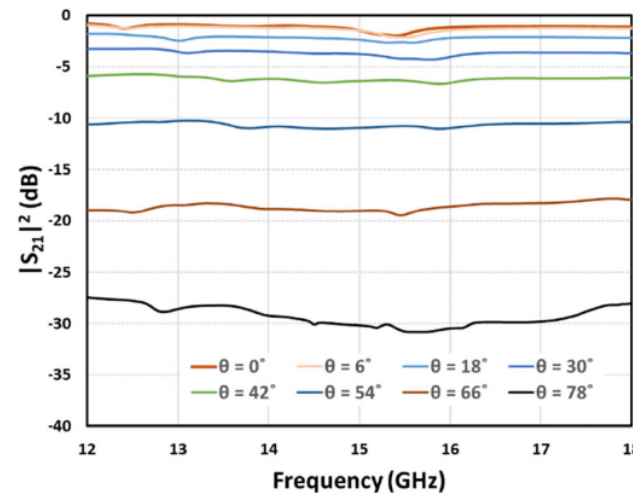
Digital Object Identifier 10.1109/ACCESS.2021.3087012

Microwave Characterization of Conductive PLA and Its Application to a 12 to 18 GHz 3-D Printed Rotary Vane Attenuator

ENRIQUE MÁRQUEZ-SEGURA^{1,2}, (Senior Member, IEEE),
SANG-HEE SHIN², (Graduate Student Member, IEEE),
ATTIQUE DAWOOD², NICK M. RIDLER³, (Fellow, IEEE),
AND STEPAN LUCYSZYN², (Fellow, IEEE)



Performance Parameter	This Work (3-D Printed)	Commercial (Machined)
Attenuation Range (dB)	0-27	0-60
Maximum Insertion Loss (dB)	1.2	0.3
Worst-Case Return Loss (dB)	17 (12.7 to 18 GHz)	23
Mass (kg)	0.050	3.4



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Received January 20, 2021, accepted February 3, 2021, date of publication February 8, 2021, date of current version February 19, 2021.

Digital Object Identifier 10.1109/ACCESS.2021.3057606

Polymer-Based 3-D Printed 140-220 GHz Low-Cost Quasi-Optical Components and Integrated Subsystem Assembly

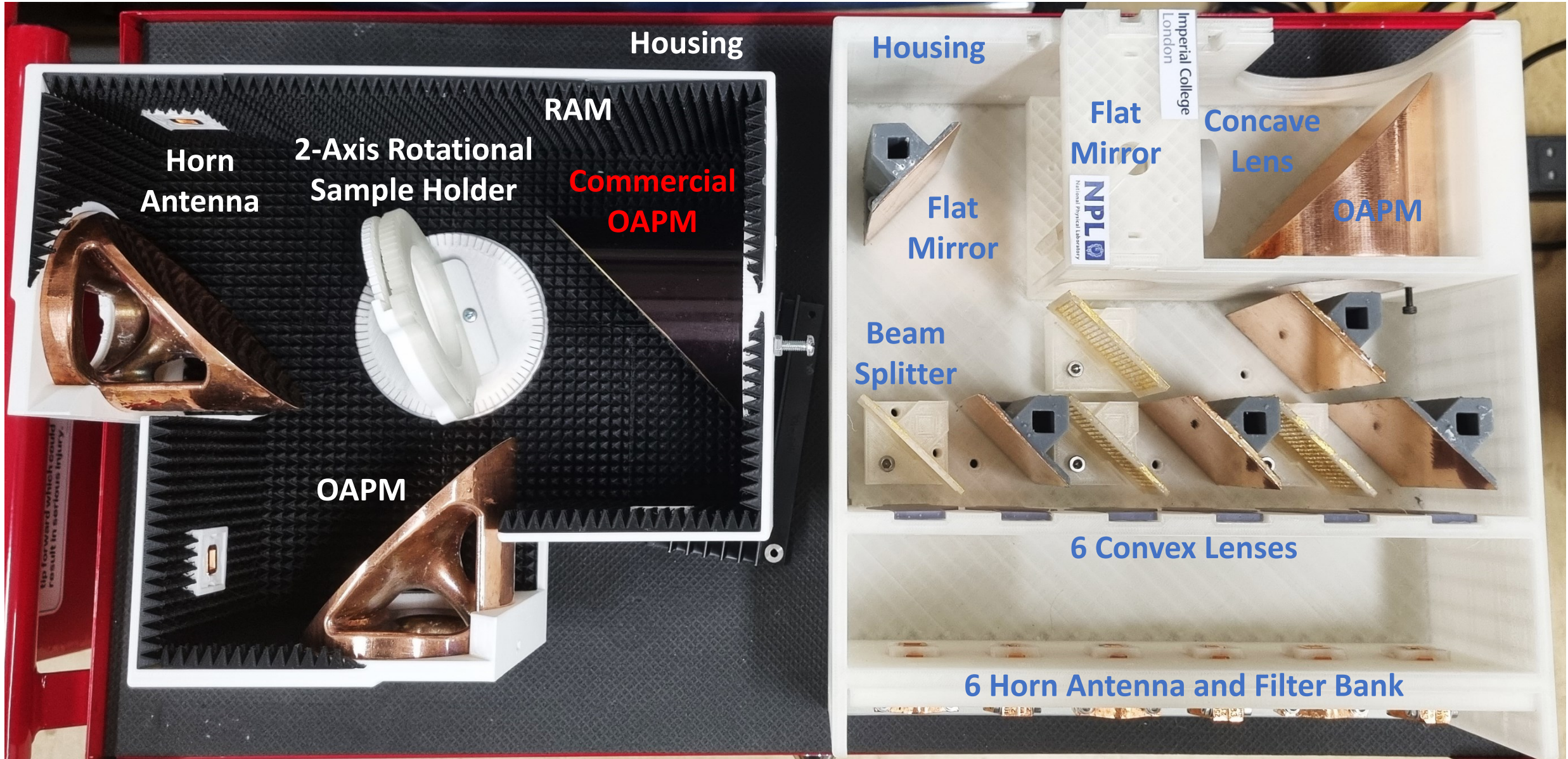
**SANG-HEE SHIN^{ID1}, (Graduate Student Member, IEEE),
XIAOBANG SHANG^{ID2}, (Senior Member, IEEE), NICK M. RIDLER^{ID2}, (Fellow, IEEE),
AND STEPAN LUCYSZYN^{ID1}, (Fellow, IEEE)**

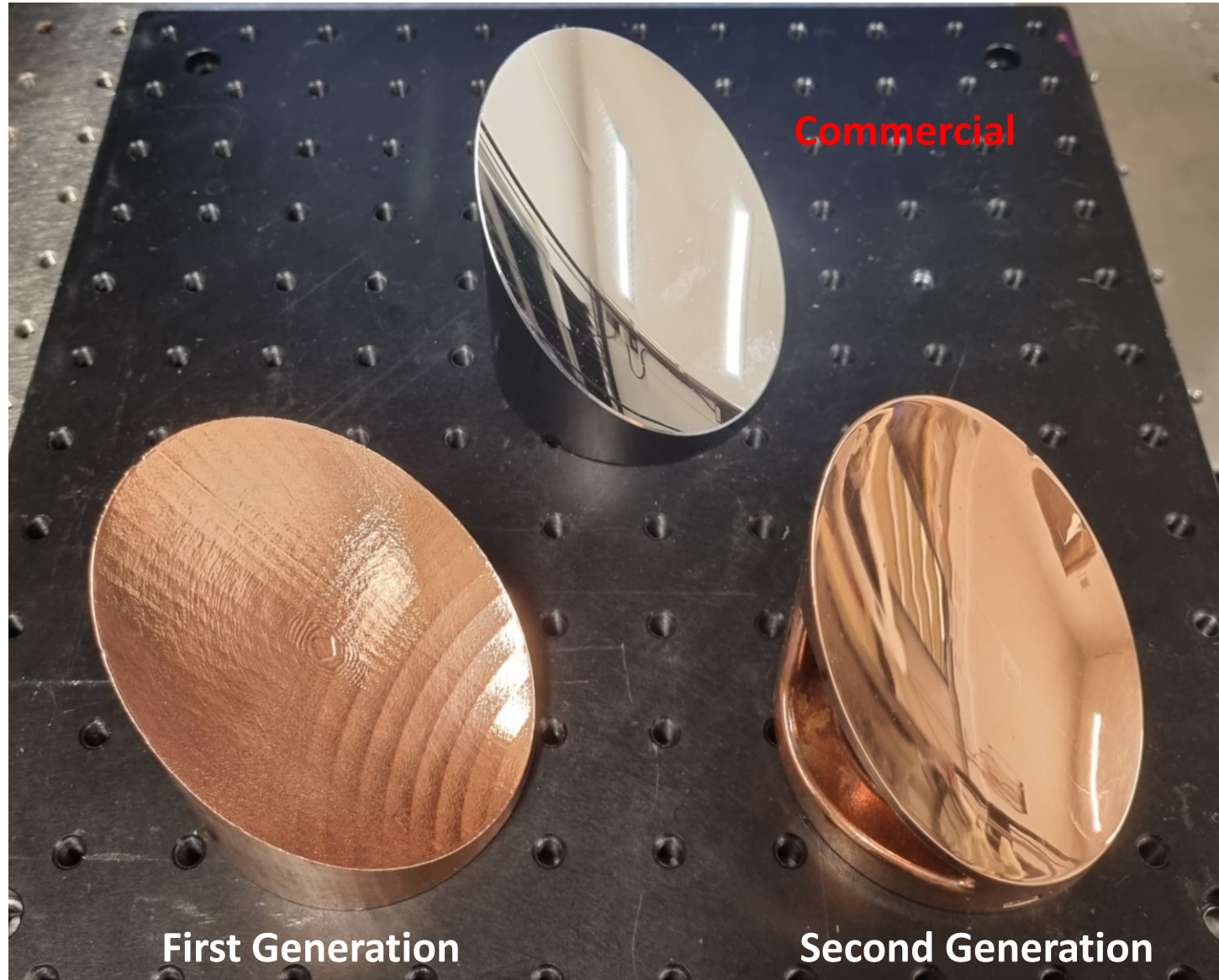
¹Department of Electrical and Electronic Engineering, Imperial College London, London SW7 2AZ, U.K.

²National Physical Laboratory, Department of Electromagnetic and Electrochemical Technologies, Teddington TW11 0LW, U.K.

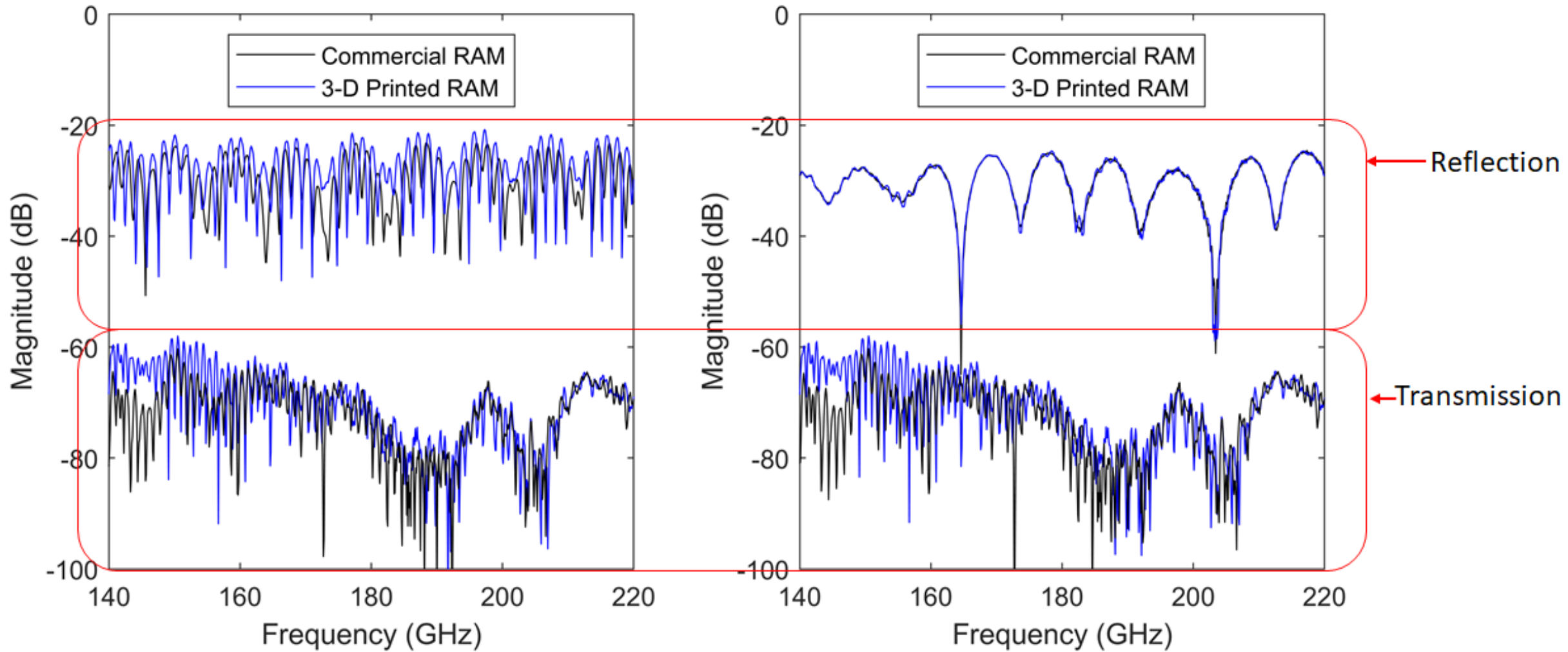
Corresponding author: Stepan Lucyszyn (s.lucyszyn@imperial.ac.uk)

This work was supported by the U.K. Space Agency's Centre for Earth Observation Instrumentation (CEOI) under Grant RP10G0435A202, and in part by the U.K. Space Agency under Grant NSTP3-FT-046.



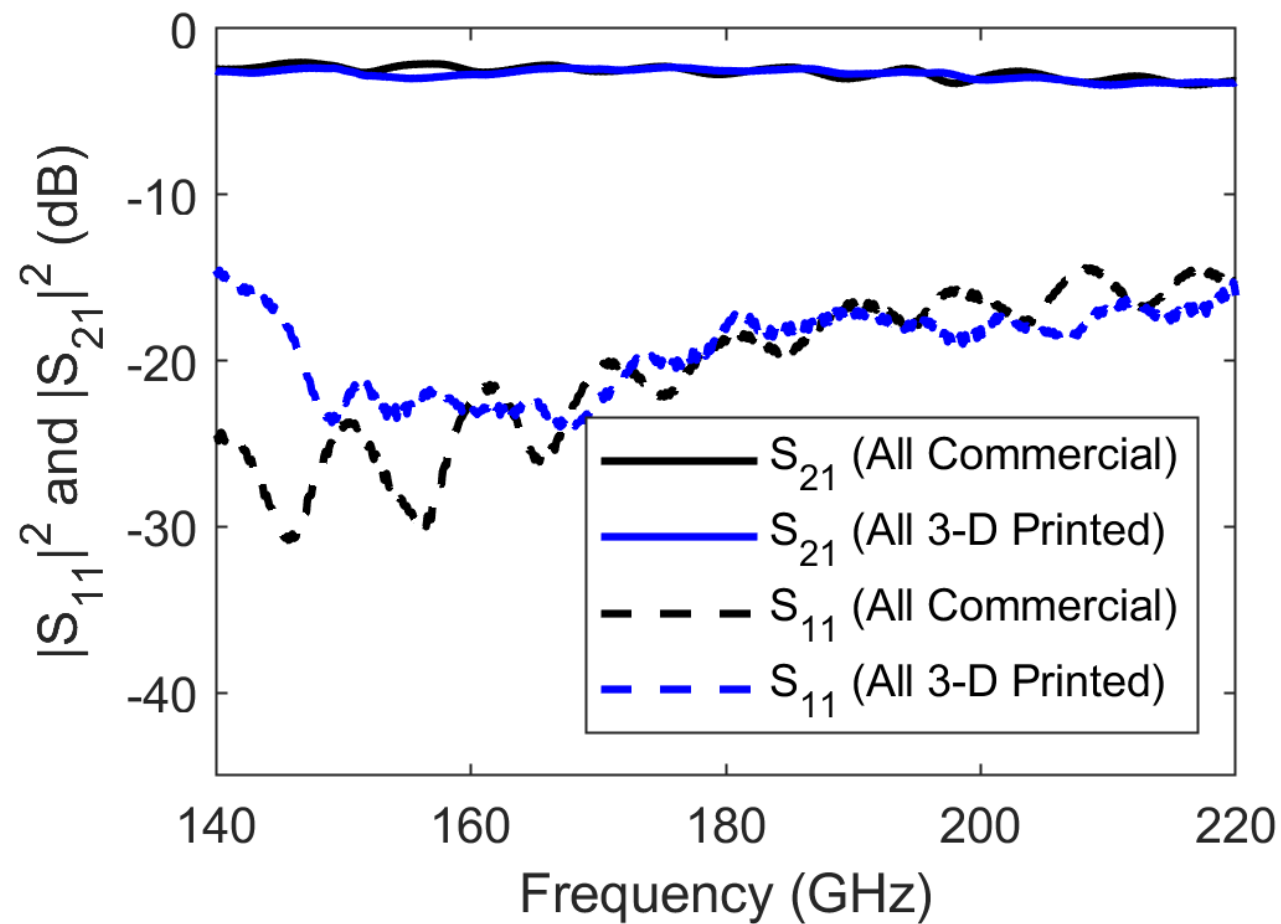
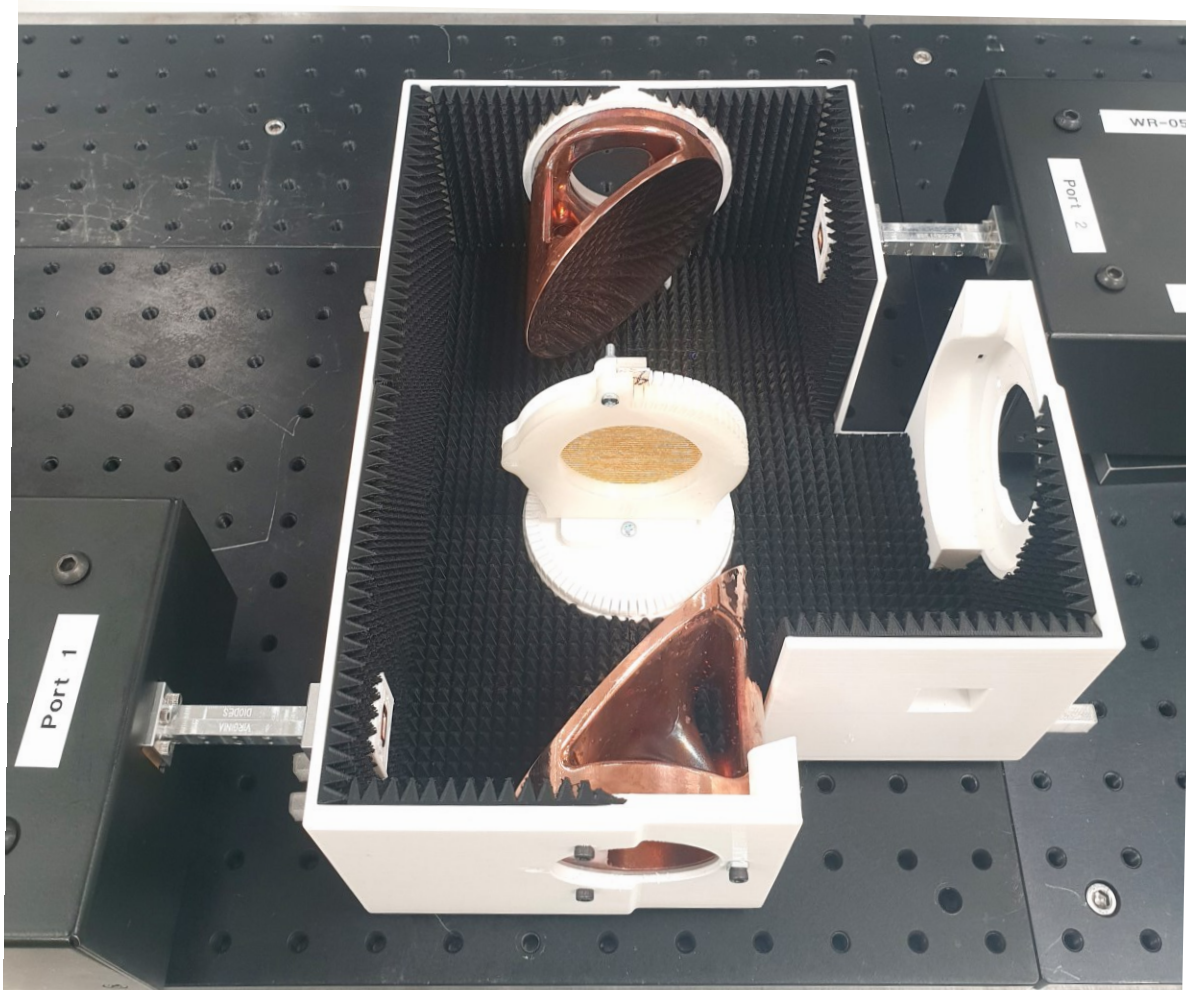


Pyramidal Radiation Absorbent Material (RAM)



Antenna Pointing at Back-Side of RAM

Antenna Pointing at Front-Side of RAM



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Received March 28, 2022, accepted April 10, 2022, date of publication April 14, 2022, date of current version April 25, 2022.

Digital Object Identifier 10.1109/ACCESS.2022.3167437

3-D Printed Plug and Play Prototyping for Low-Cost Sub-THz Subsystems

SANG-HEE SHIN^{ID1}, (Member, IEEE), **ROSHAN PAYAPULLI**¹, **LIYAN ZHU**^{ID1},
MANOJ STANLEY^{ID2}, (Member, IEEE), **XIAOBANG SHANG**^{ID2}, (Senior Member, IEEE),
NICK M. RIDLER^{ID2}, (Fellow, IEEE), AND **STEPAN LUCYSZYN**^{ID1}, (Fellow, IEEE)

¹Department of Electrical and Electronic Engineering, Imperial College London, London SW7 2AZ, U.K.

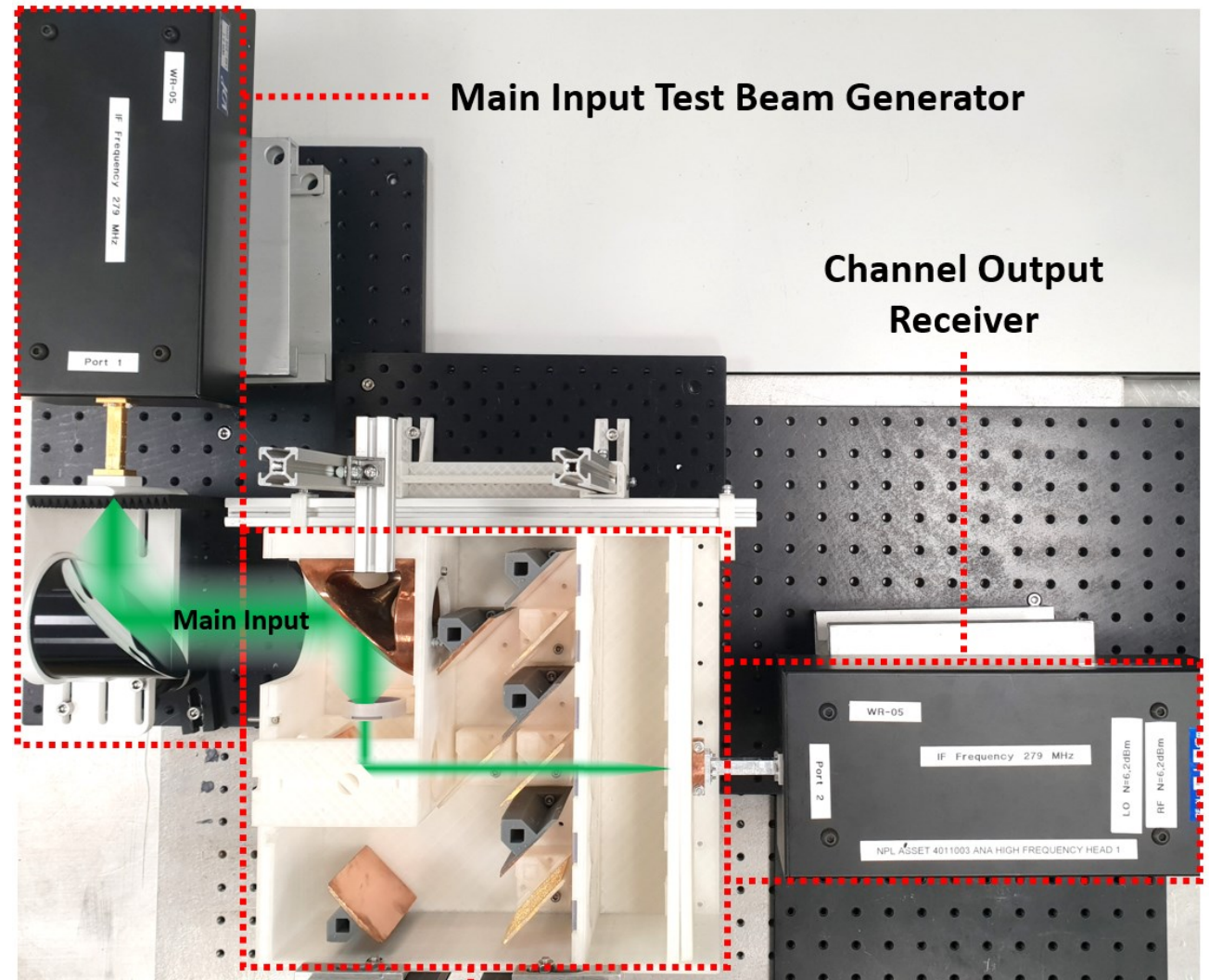
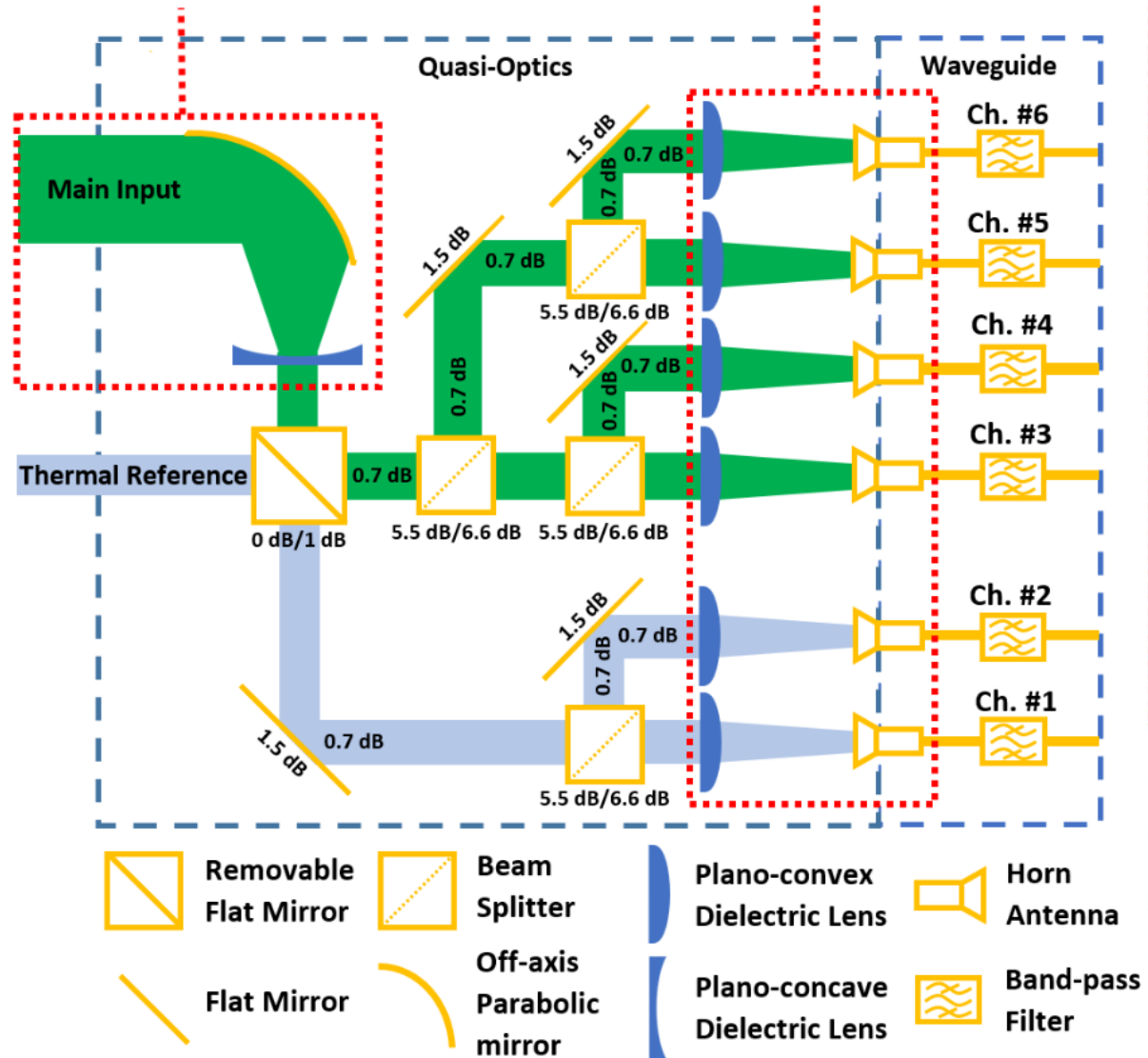
²Department of Electromagnetic and Electrochemical Technologies, National Physical Laboratory, Teddington TW11 0LW, U.K.

Corresponding author: Stepan Lucyszyn (s.lucyszyn@imperial.ac.uk)

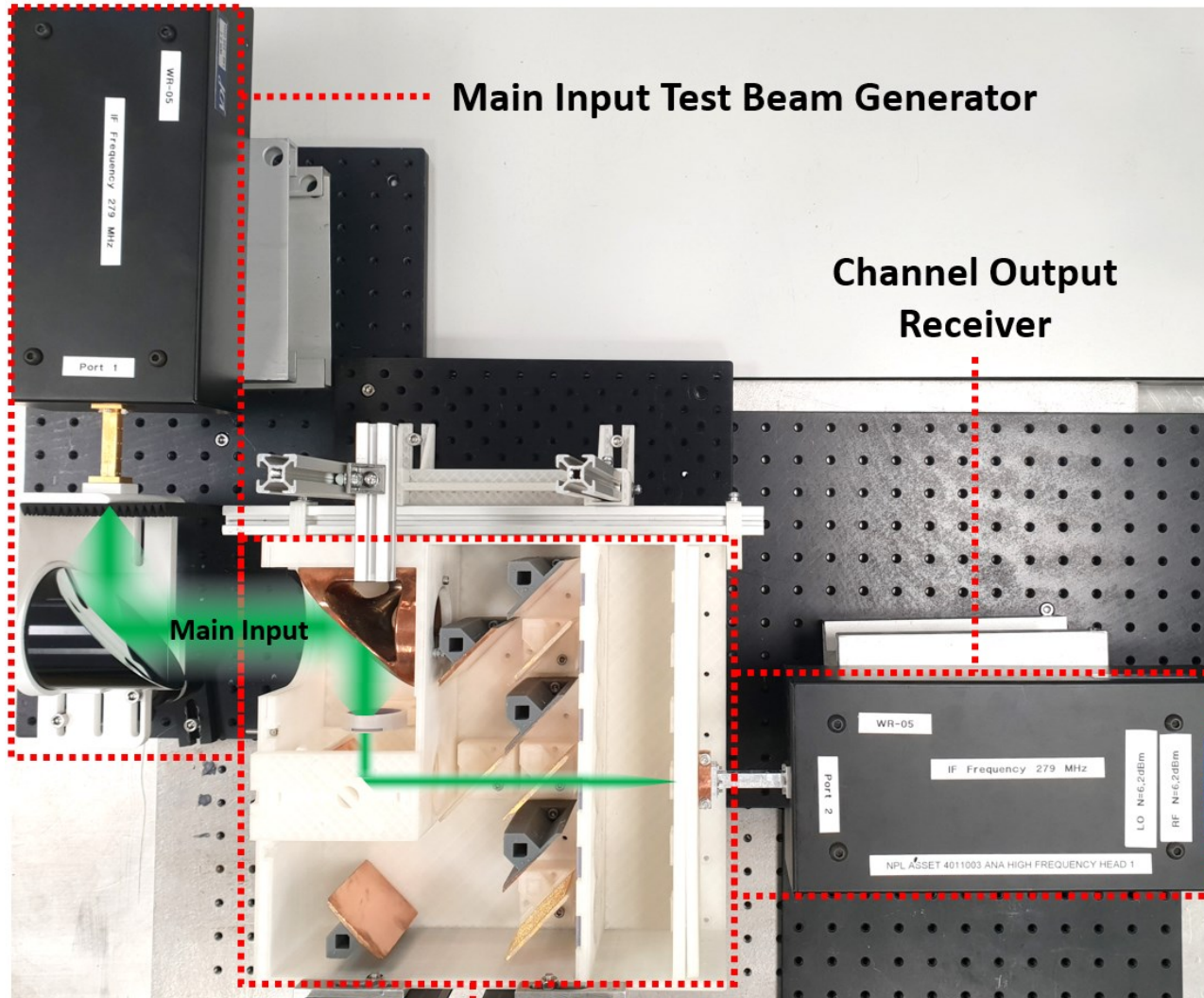
This work was supported by the U.K. Space Agency's Centre for Earth Observation Instrumentation (CEOI) under Grant RP10G0435A202.

Common Loss: 9 dB

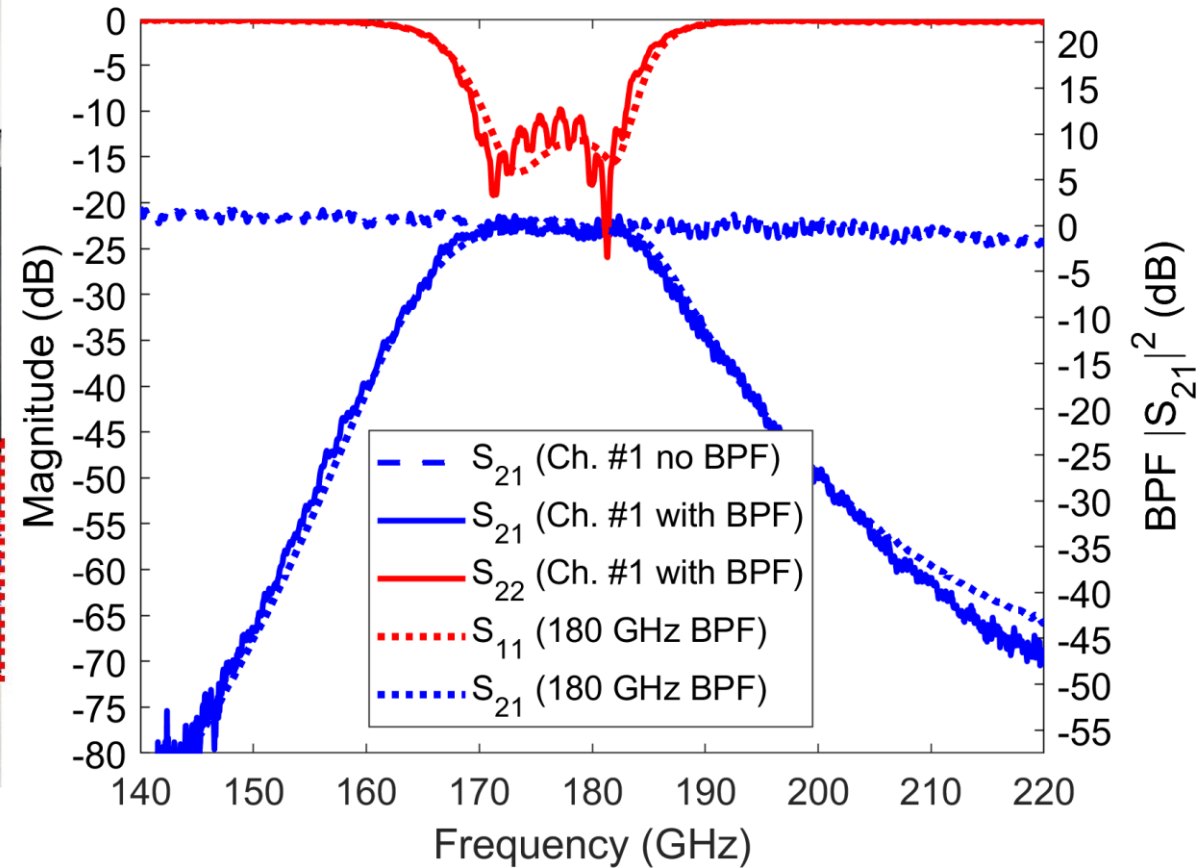
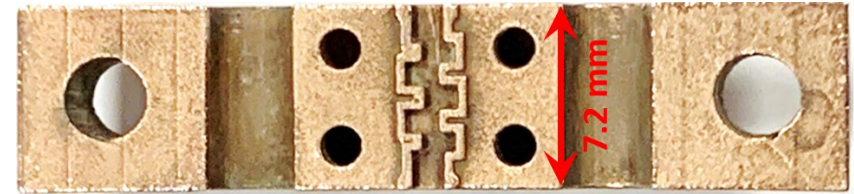
Common Loss: 6.5 dB



Assembled 3-D Printed Subsystem



Assembled 3-D Printed Subsystem

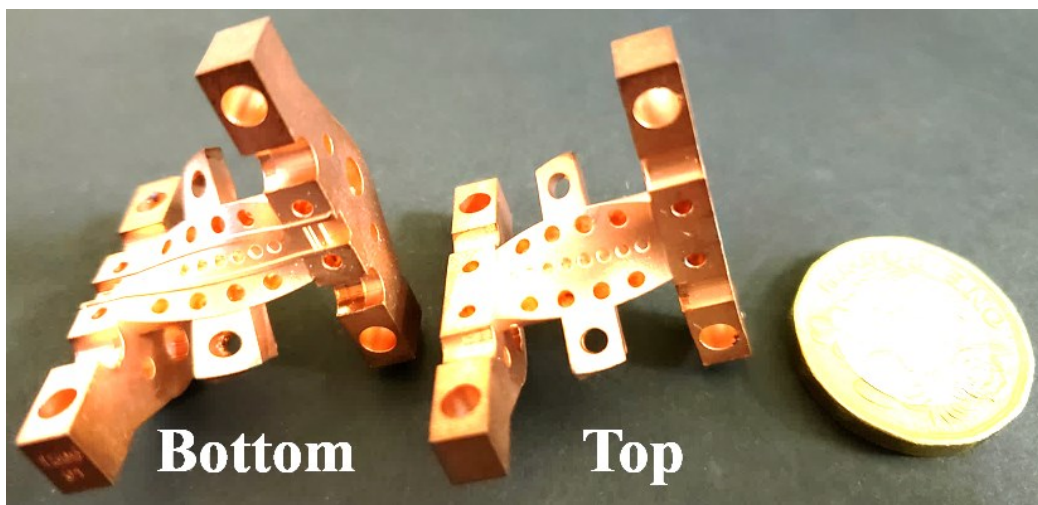
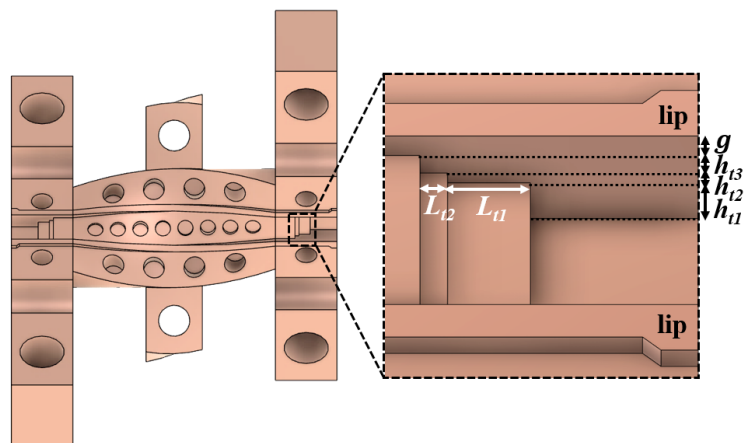
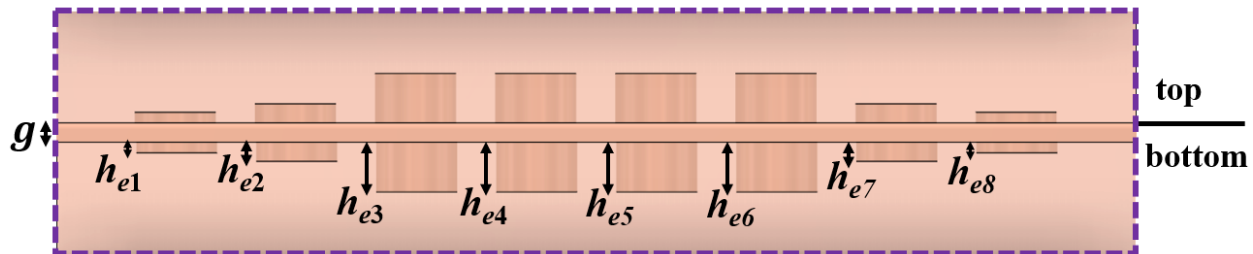


IEEE MICROWAVE AND WIRELESS TECHNOLOGY LETTERS, VOL. 33, NO. 6, JUNE 2023

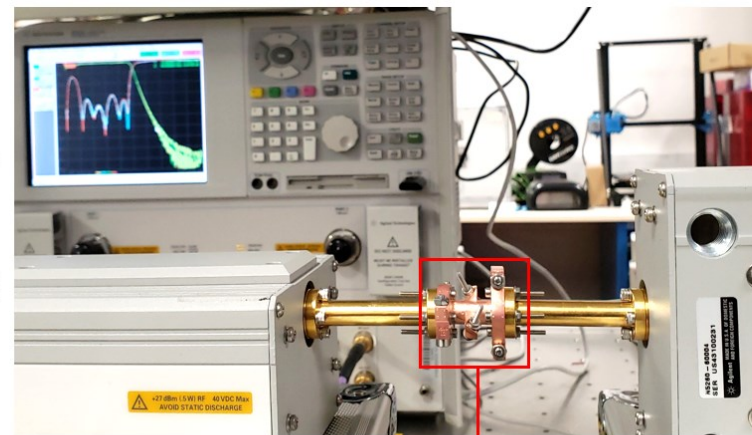
659

3-D Printed W-Band Waveguide Twist With Integrated Filtering

Liyan Zhu^{ID}, Ian W. Rossuck, Roshan Payapulli, Sang-Hee Shin^{ID}, *Member, IEEE*,
and Stepan Lucyszyn^{ID}, *Fellow, IEEE*

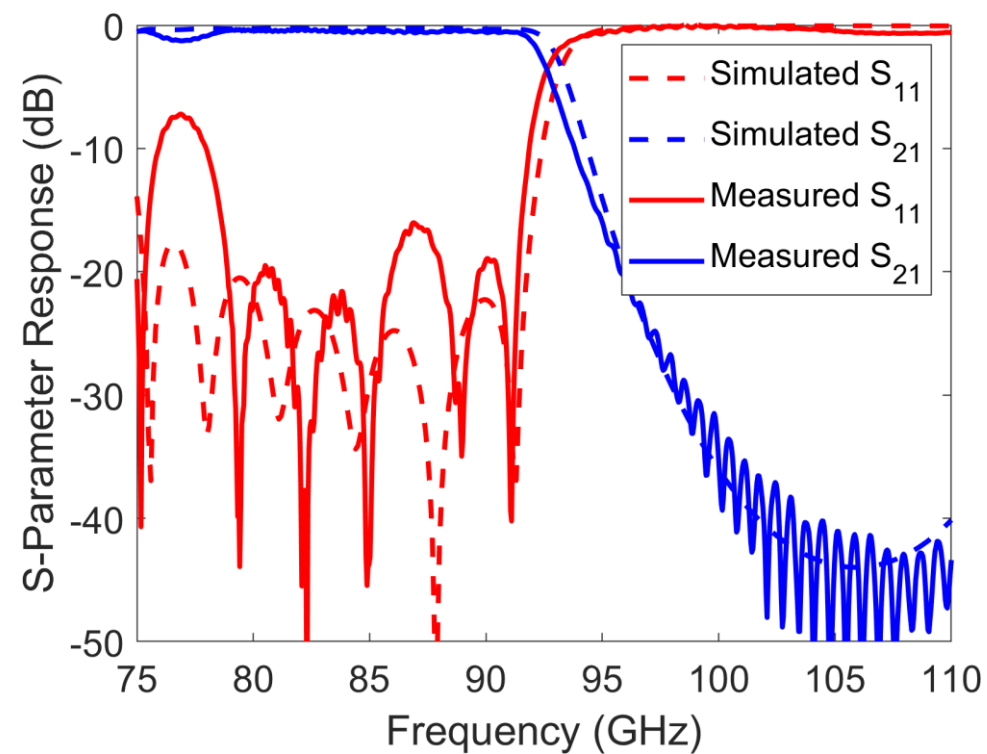


VNA extension head
(port 1)



VNA extension head
(port 2)

3-D printed waveguide twist-filter



IEEE MICROWAVE AND WIRELESS TECHNOLOGY LETTERS, VOL. 33, NO. 2, FEBRUARY 2023

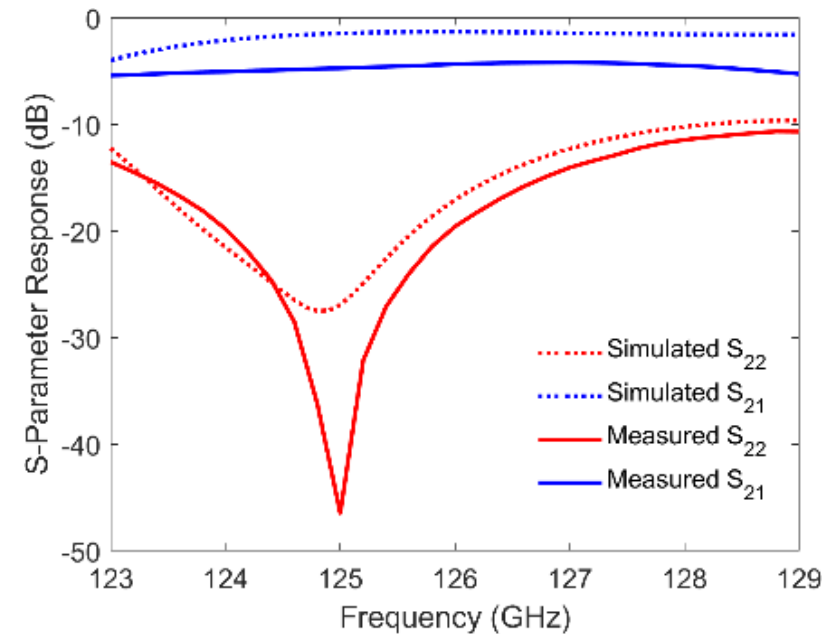
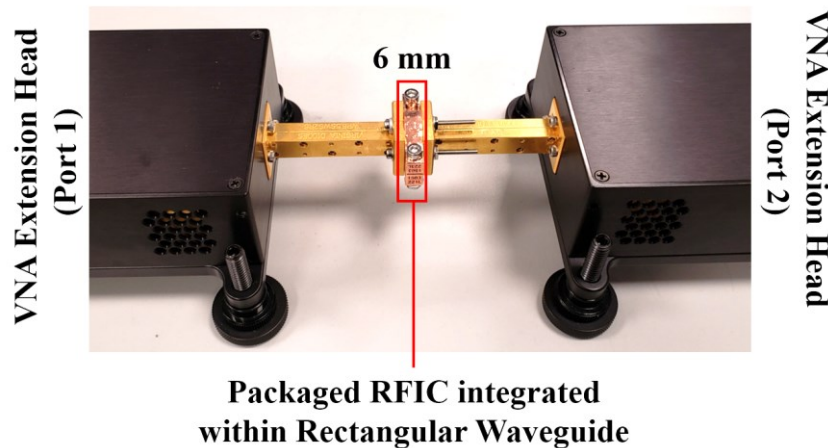
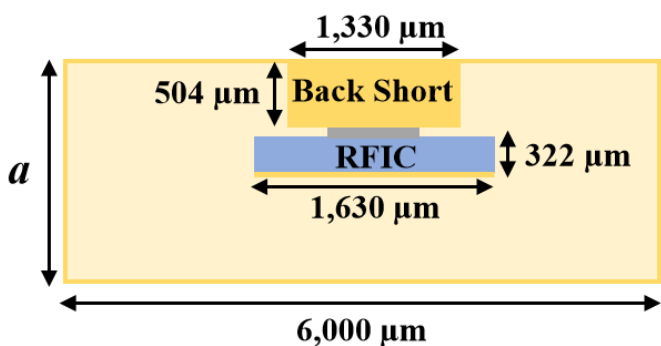
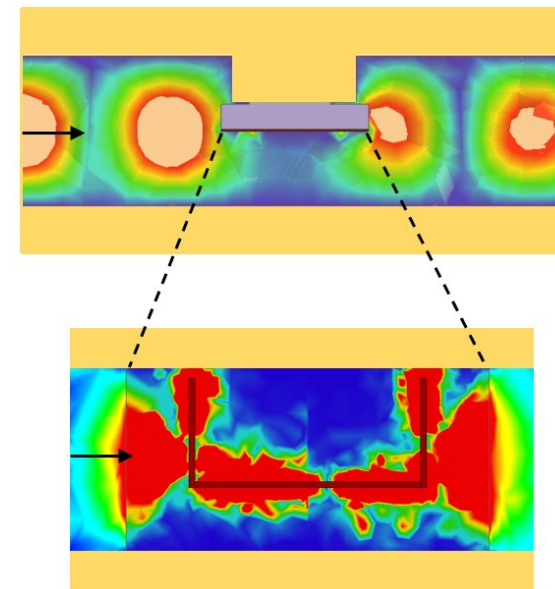
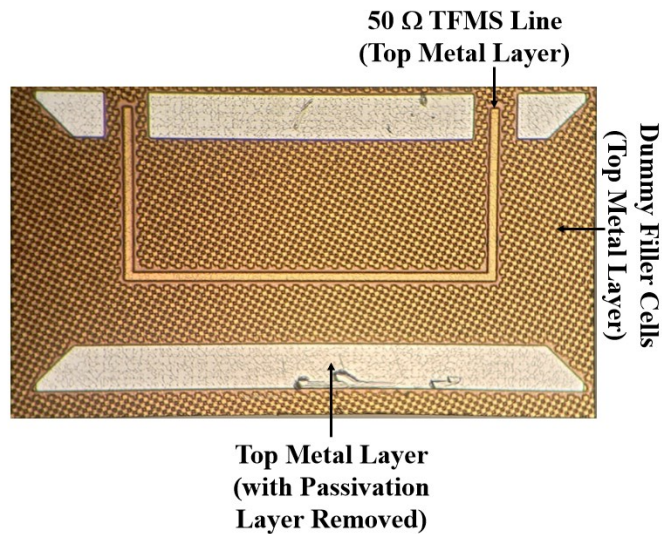
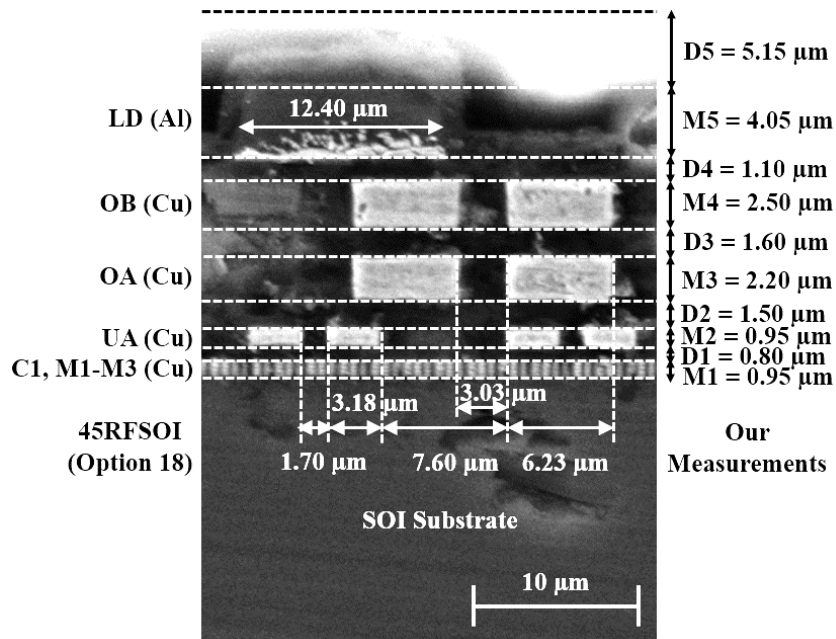
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3-D Printed Rectangular Waveguide 123–129 GHz Packaging for Commercial CMOS RFICs

Liyan Zhu^{ID}, Sang-Hee Shin^{ID}, *Member, IEEE*, Roshan Payapulli, Taiki Machii,
Mizuki Motoyoshi^{ID}, *Member, IEEE*, Noriharu Suematsu, *Senior Member, IEEE*,
Nick M. Ridler^{ID}, *Fellow, IEEE*, and Stepan Lucyszyn^{ID}, *Fellow, IEEE*



TOHOKU
UNIVERSITY



GlobalFoundries® 45 nm CMOS RFIC: SEM microphotograph and optical microphotograph showing 20- μm wide 50 Ω TFMS line

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Received 16 January 2023, accepted 21 March 2023, date of publication 23 March 2023, date of current version 4 April 2023.

Digital Object Identifier 10.1109/ACCESS.2023.3261241

 **RESEARCH ARTICLE**

Polymer-Based 3-D Printed 140 to 220 GHz Metal Waveguide Thru Lines, Twist and Filters

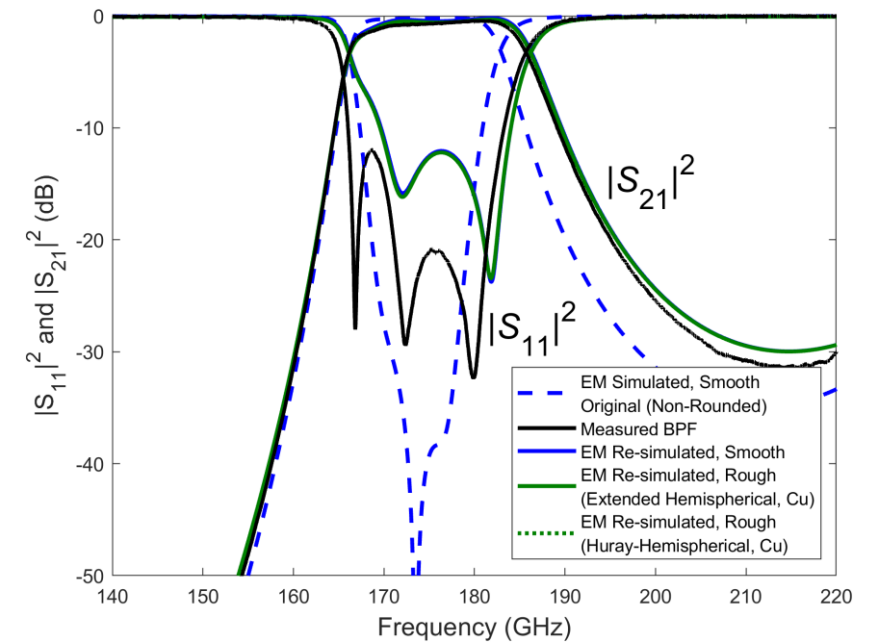
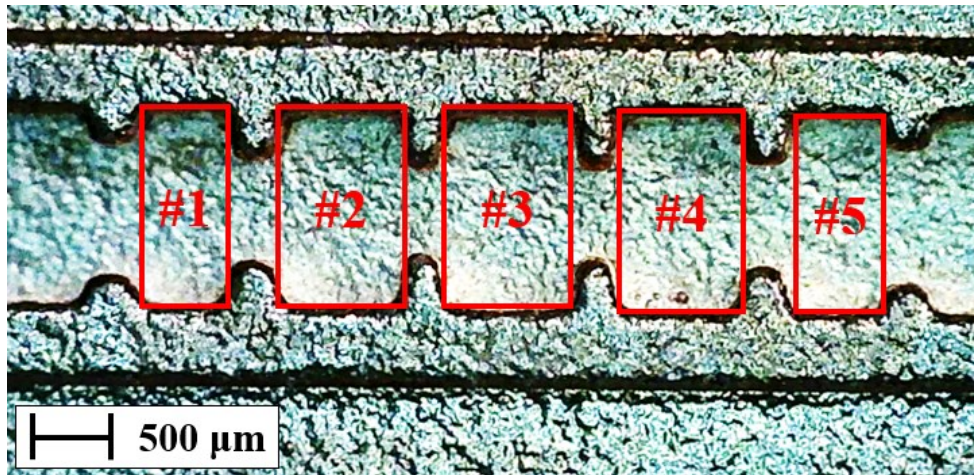
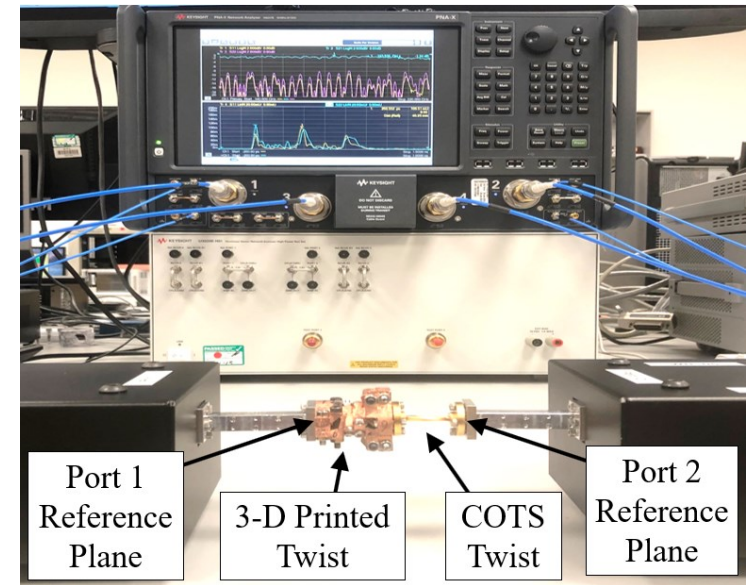
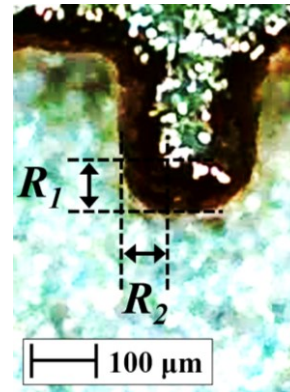
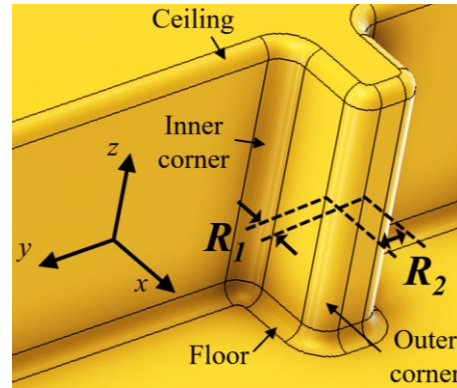
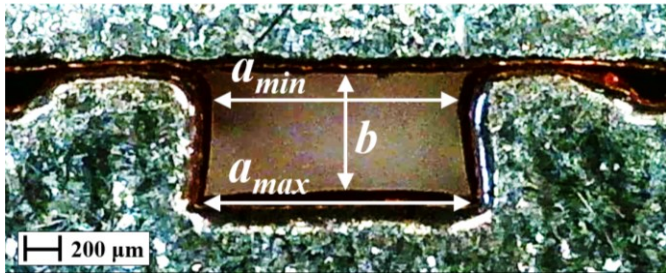
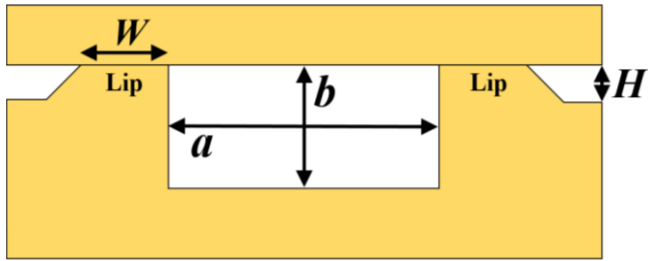
**ROSHAN PAYAPULLI¹, LIYAN ZHU^{ID1}, SANG-HEE SHIN^{ID1,2}, (Member, IEEE),
MANOJ STANLEY^{ID2}, (Member, IEEE), NICK M. RIDLER^{ID2}, (Fellow, IEEE),
AND STEPAN LUCYSZYN^{ID1}, (Fellow, IEEE)**

¹Department of Electrical and Electronic Engineering, Imperial College London, SW7 2AZ London, U.K.

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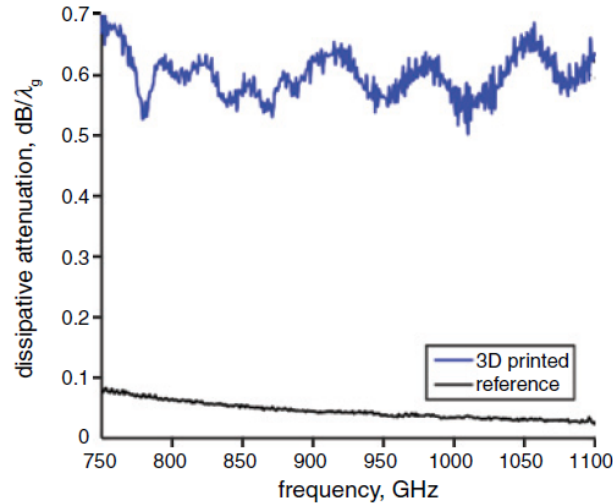
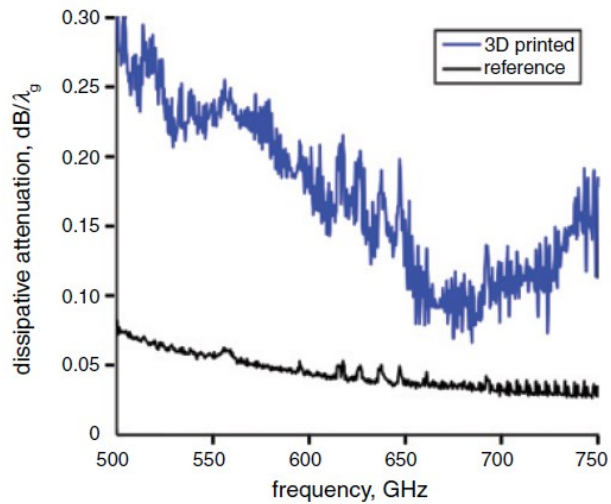
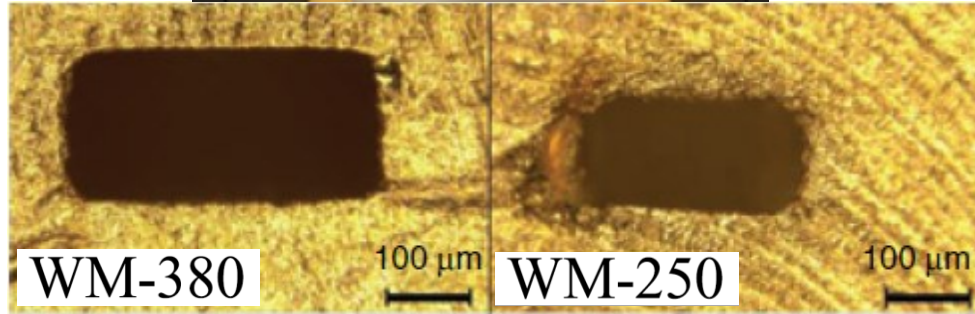
Corresponding author: Stepan Lucyszyn (s.lucyszyn@imperial.ac.uk)

This work was supported by the U.K. Space Agency's Centre for Earth Observation Instrumentation (CEOI) under Grant RP10G0435A202.



3D printed 1.1 THz waveguides

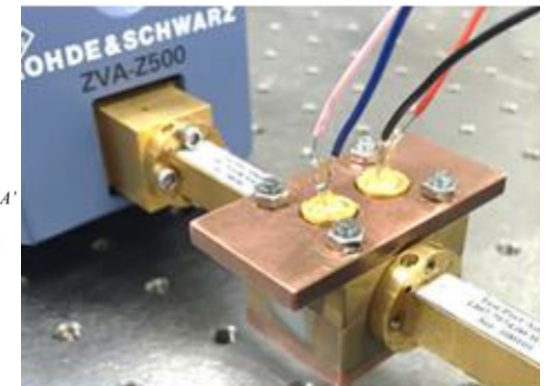
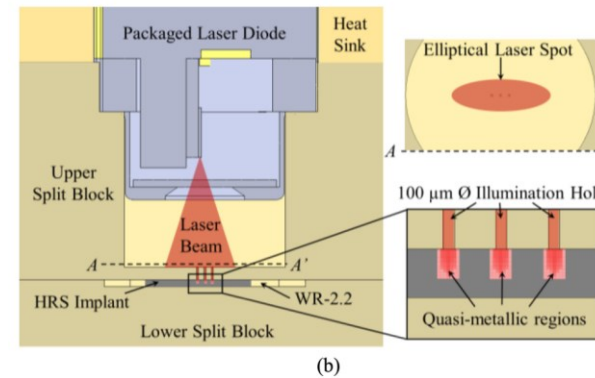
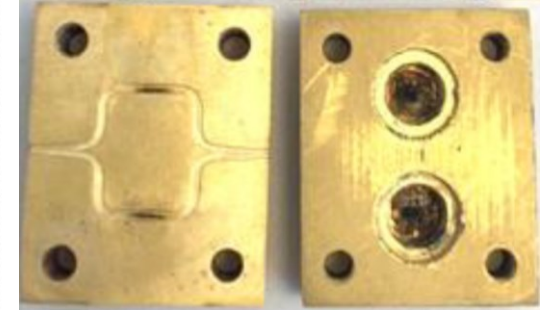
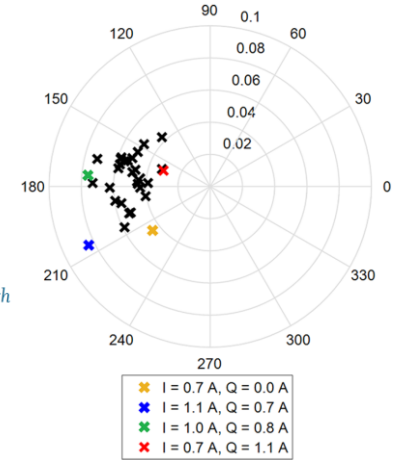
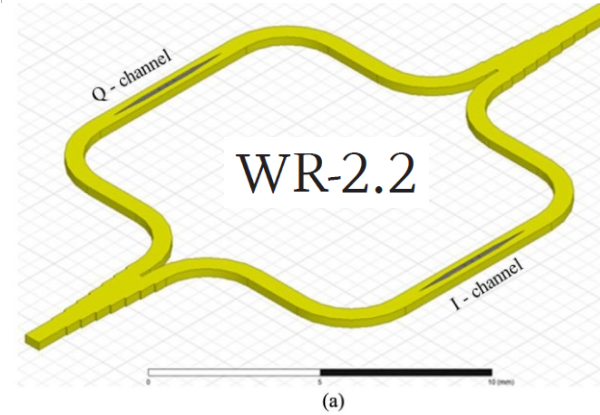
W.J. Otter, N.M. Ridler, H. Yasukochi, K. Soeda, K. Konishi, J. Yumoto, M. Kuwata-Gonokami and S. Lucyszyn[✉]



Hybrid 3-D-Printing Technology for Tunable THz Applications

In this paper, a hybrid manufacturing approach is presented that combines metallized passive components produced through the polymer-jetting process with active semiconductor devices. The potential for producing low-cost THz communication systems using this methodology is demonstrated with the successful development of a THz I-Q vector modulator.

By WILLIAM J. OTTER Member, IEEE, AND STEPAN LUCYSZYN Fellow, IEEE



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RESEARCH ARTICLE

3-D Printed THz Waveguide Components

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IAN W. ROSSUCK¹, NORBERT KLEIN³, NICK M. RIDLER², (Fellow, IEEE),
AND STEPAN LUCYSZYN¹, (Fellow, IEEE)**

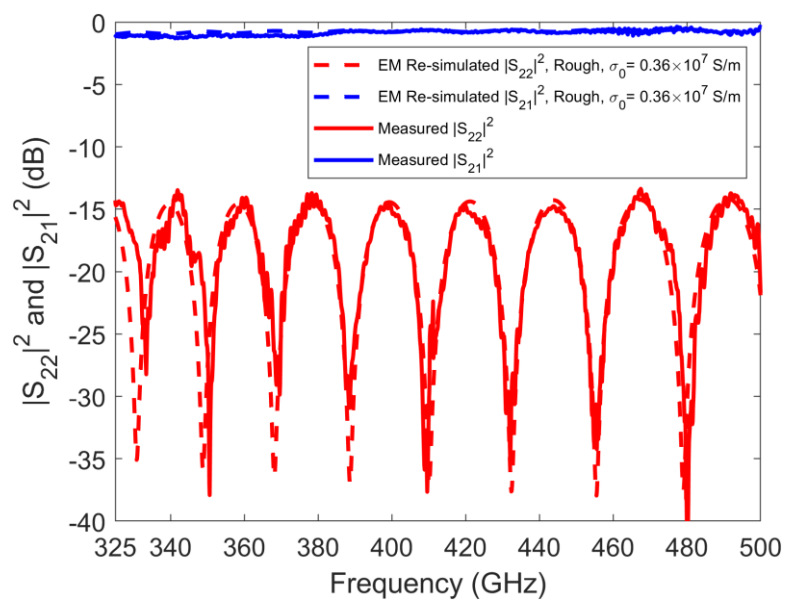
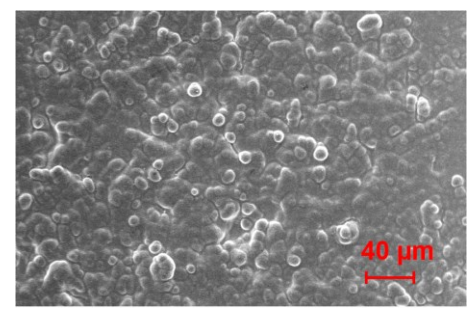
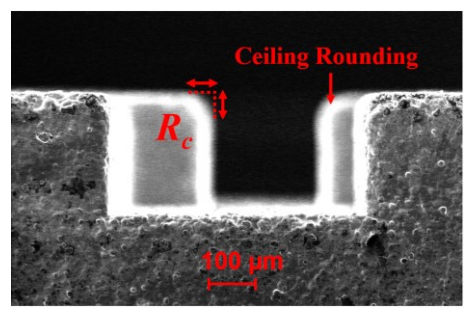
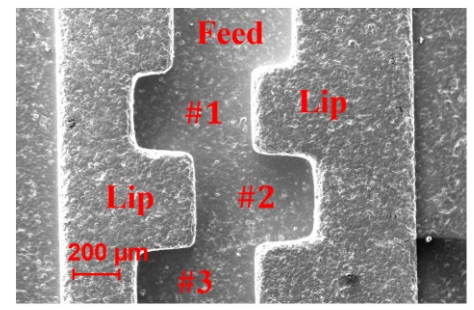
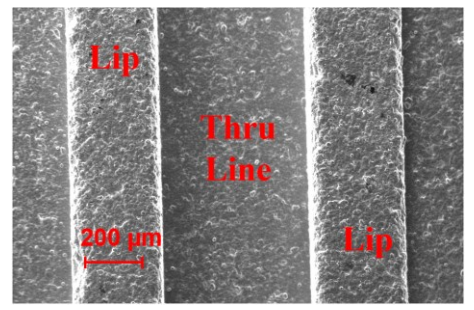
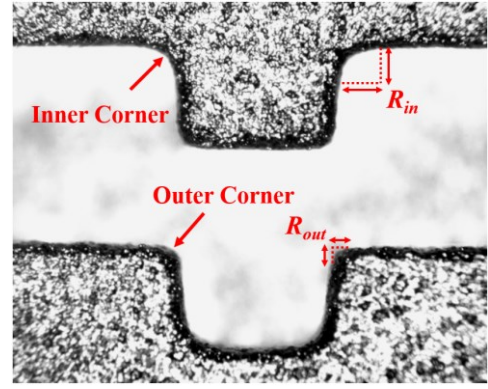
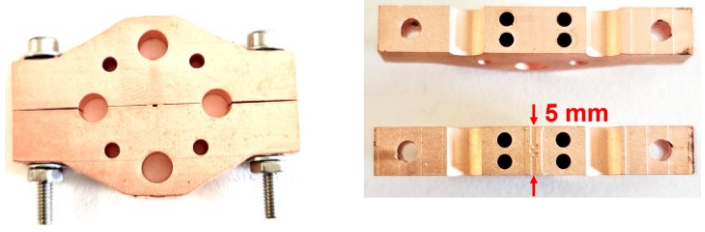
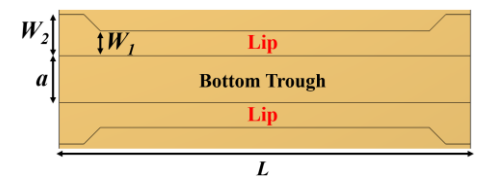
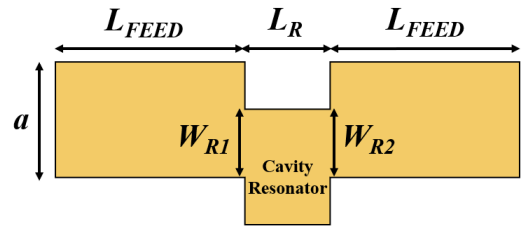
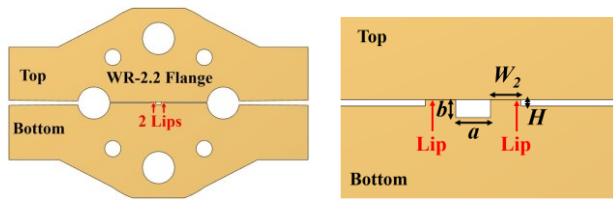
¹Department of Electrical and Electronic Engineering, Imperial College London, SW7 2AZ London, U.K.

²Department of Electromagnetic and Electrochemical Technologies, National Physical Laboratory, TW11 0LW Teddington, U.K.

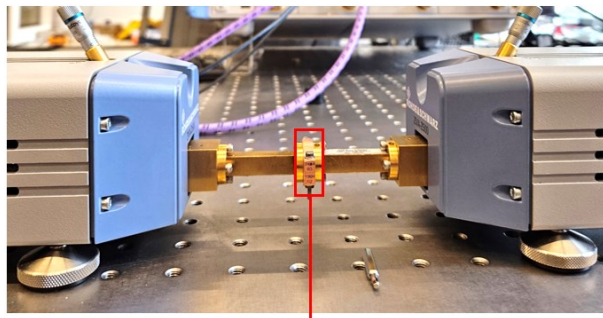
³Department of Materials, Imperial College London, SW7 2AZ London, U.K.

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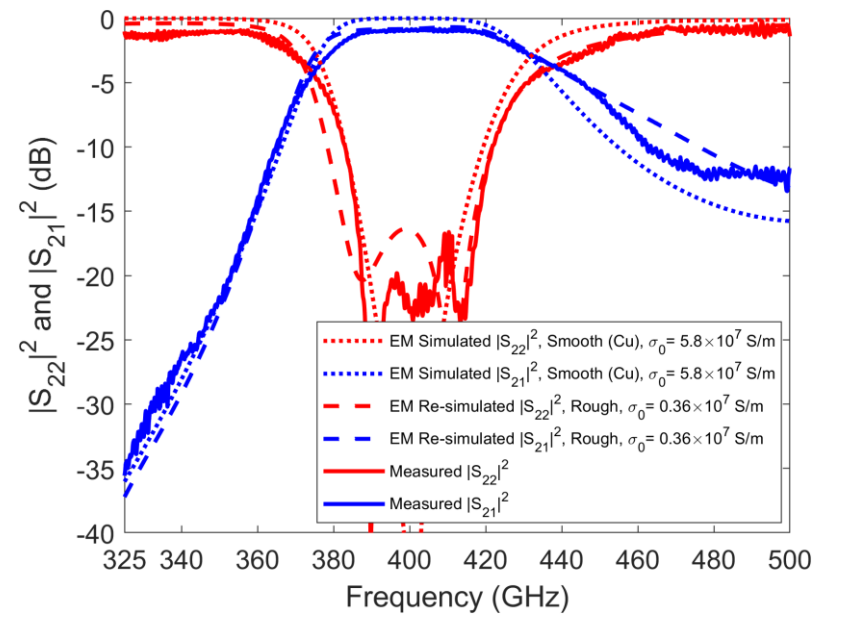
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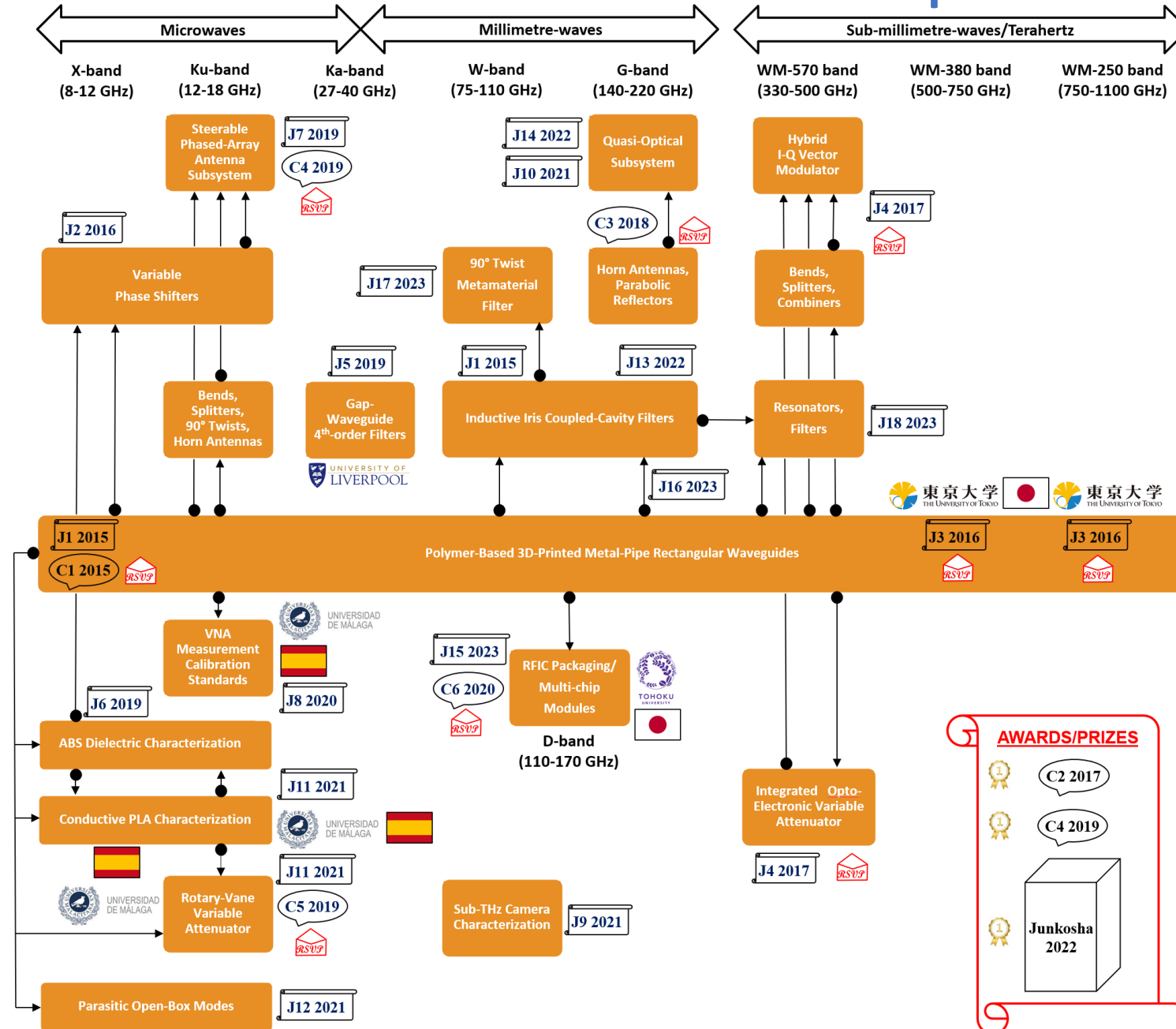
VNA Extension Head (Port 1)



VNA Extension Head (Port 2)



Publications Landscape



- J1.** M. D'Auria, W. J. Otter, J. Hazell, B. T. W. Gillatt, C. Long-Collins, N. M. Ridler, and S. Lucyszyn, "3-D printed metal-pipe rectangular waveguides", IEEE Transactions on Components, Packaging and Manufacturing Technology, vol. 5, no. 9, pp. 1339-1349, Sep. 2015 (**Most Popular T-CPMT Article, Xplore® Usage Statistics, Nov. 2019**).
- C1.** W. J. Otter and S. Lucyszyn, "3-D printing of microwave components for 21st century applications", IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes for RF and THz Applications (IMWS-AMP 2016), Chengdu, China, Jul. 2016 (**Invited**).
- J2.** B. T. W. Gillatt, M. D'Auria, W. J. Otter, N. M. Ridler, and S. Lucyszyn, "3-D printed variable phase shifter", IEEE Microwave and Wireless Component Letters, vol. 26, no.10, pp. 822-824, Oct. 2016.
- J3a.** W. J. Otter and S. Lucyszyn, "Printing: the future of THz", IET Electronics Letters, vol. 53, no. 7, p. 433, Mar. 2017 (**Invited Feature Article**).
- J3b.** W. J. Otter, N. M. Ridler, H. Yasukochi, K. Soeda, K. Konishi, J. Yumoto, M. Kuwata-Gonokami, and S. Lucyszyn, "3D printed 1.1 THz waveguides", IET Electronics Letters, vol. 53, no. 7, pp. 471-473, Mar. 2017.
- C2.** W. J. Otter, N. M. Ridler, and S. Lucyszyn, "3D printed waveguides: A revolution in low volume manufacturing for the 21st century", ARMMS RF & Microwave Society Conference, Nr Thame, UK, pp. 1-6, Apr. 2017 (**Best Paper Award**).
- J4.** W. J. Otter and S. Lucyszyn, "Hybrid 3-D-printing technology for tunable THz applications", Proceedings of IEEE, Special Issue on Additive Manufacturing of Radio-Frequency Components, vol. 105, no. 4, pp. 756-767, Apr. 2017 (**Invited**).
- C3.** S. Lucyszyn, X. Shang, W. J. Otter, C. Myant, R. Cheng, and N. M. Ridler, "Polymer-based 3D printed millimeter-wave components for spacecraft payloads", IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes (IMWS-AMP), Ann Arbor, USA, Jul. 2018 (**Invited**).
- J5.** B. Al-Juboori, J. Zhou, Y. Huang, M. Hussein, A. Alieldin, W. J. Otter, D. Klugmann, and S. Lucyszyn, "Lightweight and low-loss 3-D printed millimeter-wave bandpass filter based on gap-waveguide", IEEE Access, vol. 7, no. 1, pp. 2624-2632, Jan. 2019.
- J6.** J. Sun, A. Dawood, W. J. Otter, N. M. Ridler, and S. Lucyszyn, "Microwave characterization of low-loss FDM 3-D printed ABS with dielectric-filled metal-pipe rectangular waveguide spectroscopy", IEEE Access, vol. 7, pp. 95455-95486, Jul. 2019.
- C4.** S.-H. Shin, D. Alyasiri, M. D'Auria, W. J. Otter, C. W. Myant, D. Stokes, Z. Tian, N. M. Ridler, and S. Lucyszyn, "Fully 3-D printed tunable microwave subsystem," IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes (IMWS-AMP), Bochum, Germany, Jul. 2019 (**Invited and Best Student Paper Award**).
- J7.** S.-H. Shin, D. Alyasiri, M. D'Auria, W. J. Otter, C. W. Myant, D. Stokes, Z. Tian, N. M. Ridler, and S. Lucyszyn, "Polymer-based 3-D printed Ku-band steerable phased-array antenna subsystem", IEEE Access, vol. 7, pp. 106662-106673, Aug. 2019.
- C5.** E. Márquez-Segura, W. J. Otter, and S. Lucyszyn, N. Ridler, "Fabrications aditiva de atenuadores variables de veleta rotatoria en guía de onda", XXXIV Simposium Nacional de la Unión Científica Internacional de Radio (URSI 2019), Sevilla, Spain, Sep. 2019 (**Invited**).
- J8.** A. Jones, S. Lucyszyn, E. Márquez-Segura, N. Ridler, J. Skinner, and D. Stokes, "3-D printed primary standards for calibration of microwave network analysers", Measurement, Elsevier, vol. 158, no. 107682, pp. 1-10, Jul. 2020
- C6.** S. Lucyszyn, L. Zhu, T. Machii, M. Motoyoshi and N. Suematsu, "Towards 3-D printed (sub-)THz active device packaging and multi-chip modules", 2020 IEEE International Symposium on Radio-Frequency Integrated Technology (RFIT2020), Hiroshima, Japan, Sep. 2020 (**Invited**).

- J9.** S.-H. Shin and S. Lucyszyn, "Benchmarking a commercial (sub-)THz focal plane array against a custom-built millimeter-wave single-pixel camera", IEEE Access, vol. 8, pp. 191174-191190, Oct. 2020.
- J10.** S.-H. Shin, X. Shang, N. M. Ridler, and S. Lucyszyn, "Polymer-based 3-D printed 140-220 GHz low-cost quasi-optical components and integrated subsystem assembly", IEEE Access, vol. 9, pp. 28020-28038, Feb. 2021.
- J11.** E. Márquez-Segura, S.-H. Shin, A. Dawood, N. Ridler, and S. Lucyszyn, "Microwave characterization of conductive PLA and its application to a 12 to 18 GHz 3-D printed rotary vane attenuator", IEEE Access, vol. 9, pp. 84327- 84343, Jun. 2021.
- J12.** A. Dawood and S. Lucyszyn, "Parasitic high Q-factor open-box modes with 3-D printed dielectric-filled metal waveguides", IEEE Access, vol. 9, pp. 134319-134334, Oct. 2021.
- J13.** L. Zhu, R. Payapulli, S.-H. Shin, S-H, M. Stanley, N. M. Ridler, S. Lucyszyn, "3-D printing quantization predistortion applied to sub-THz chained-function filters", IEEE Access, vol. 10, pp. 38944-38963, Mar. 2022.
- J14.** S.-H. Shin, R. Payapulli, L. Zhu, M. Stanley, X. Shang, N. M. Ridler, and S. Lucyszyn, "3-D printed plug and play prototyping for low-cost sub-THz subsystems", IEEE Access, vol. 10, pp. 41708-41719, Apr. 2022.
- J15.** L. Zhu, S.-H. Shin, R. Payapulli, T. Machii, M. Motoyoshi, N. Suematsu, N. M. Ridler, and S. Lucyszyn, "3-D printed rectangular waveguide 123-129 GHz packaging for commercial CMOS RFICs", IEEE Microwave and Wireless Technology Letters, vol. 33, no. 2, pp. 157-160, Feb. 2023.
- J16.** R. Payapulli, L. Zhu, S.-H. Shin, M. Stanley, N. M. Ridler, and S. Lucyszyn, "Polymer-based 3-D printed 140 to 220 GHz metal waveguide thru lines, twist and filters", IEEE Access, vol. 11, pp. 32272-32295, Apr. 2023.
- J17.** L. Zhu, I. Rossuck, R. Payapulli, S.-H. Shin, and S. Lucyszyn, "3-D printed W-band waveguide twist with integrated filtering", IEEE Microwave and Wireless Technology Letters, vol. 33, no. 6, pp. 659-662, Jun. 2023.
- J18.** L. Zhu, S.-H. Shin, R. Payapulli, I. W. Rossuck, N. Klein, N. M. Ridler, and S. Lucyszyn, "3-D Printed THz Waveguide Components", IEEE Access, vol. 11, pp. 79073-79086, Aug. 2023.



Prizes



William Otter receives the Steve Evans-Pughe Memorial Prize for the best paper from John Crute, ARRMS Chairman, 2017

Stepan Lucyszyn receives the category winner (Microwave and Millimeter Wave) of its inaugural Technology Innovator of the Year Awards from Joe Rowan, President and CEO of Junkosha USA Inc., 2022



IEEE MTT-S International Microwave Workshop Series on Advanced Materials and Processes for RF and THz Applications
IMWS-AMP 2019

Best Student Paper Award

presented to

Sang-Hee Shin, Diyar Alyasiri, Mario D'Auria, William Otter, Connor Myant, Daniel Stokes, Zhengrong Tian, Nick Ridler, Stepan Lucyszyn

for the paper

„Fully 3-D Printed Tunable Microwave Subsystem“

<p>IMWS-AMP Awards Chair</p> <p>Prof. Dr.-Ing. Ke Wu</p>	<p>IMWS-AMP Chair</p> <p>Prof. Dr.-Ing. Ilona Rolfes</p>	<p>IMWS-AMP TPC-Chair</p> <p>Prof. Dr.-Ing. Nils Pohl</p>
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Our Student Training at NPL



Nick Ridler
(NPL)



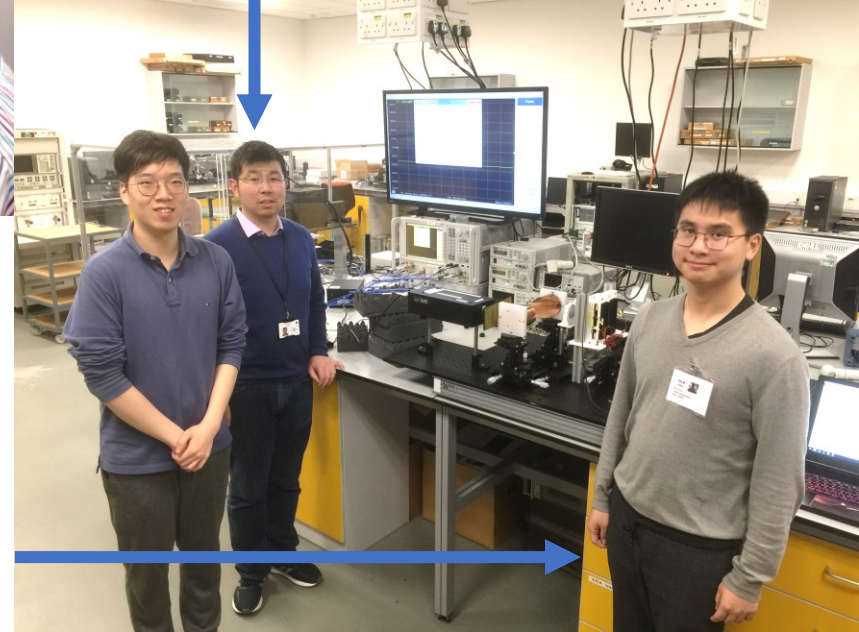
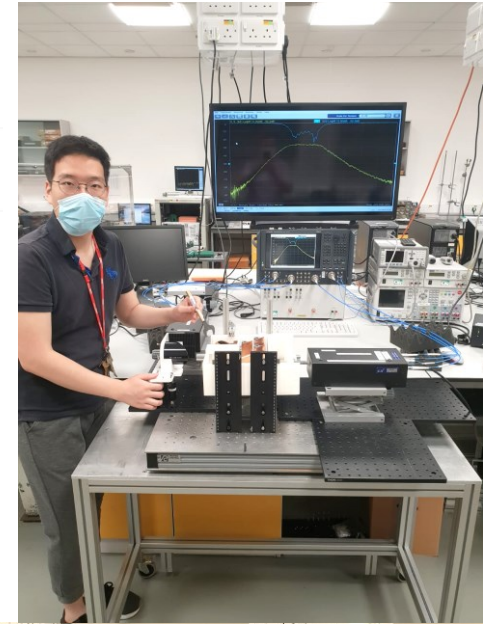
Brendan Gillatt
(Undergraduate Student)



Sang-Hee Shin
(PhD Student)
(now at NPL)



Xiaobang Shang
(NPL)



Callum Long-Collins
(Undergraduate Student)



Jonathan Hazell
(PhD Student)



ICL

Liyang Zhu
(PhD Student)



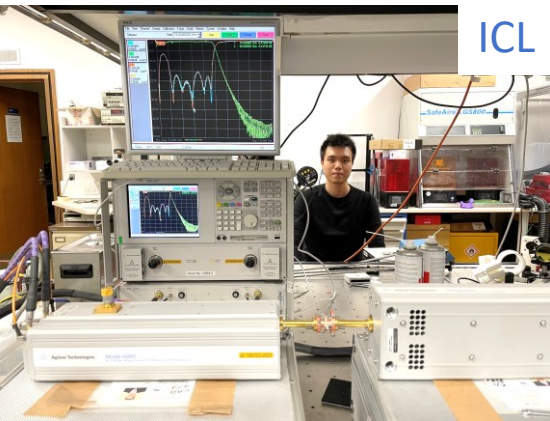
Mario D'Auria
(PhD Student)
(NPL Spin-out)



William Otter
(PhD Student)



Ran Cheng
(PhD Student)





UNIVERSITY OF
LIVERPOOL

Yi Huang
B. Al-Juboori
J. Zhou
M. Hussein
A. Alieldin
D. Klugmann



Imperial College London

PhD Students

W. J. Otter
M. D'Auria
J. Sun
A. Dawood
S.-H. Shin
R. Payapulli
L. Zhu
I. W. Rossuck

Post-doctoral
Employment

Undergraduate/MSc Students

B. T. W. Gillatt
C. Long-Collins
D. Alyasiri
A. Wietfeld (UROP, Germany)
R. Wang
X. Ju



National Physical Laboratory

Nick M. Ridler

EuMW 2021 General Chair

X. Shang
M. Stanley
J. Skinner
D. Stokes
Z. Tian
A. Jones (apprentice)



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Enrique Márquez-Segura



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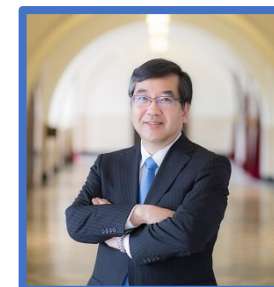
Noriharu Suematsu
L. Zhu
T. Machii
M. Motoyoshi



東京大学
THE UNIVERSITY OF TOKYO

Makoto Kuwata-Gonokami

H. Yasukochi
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